CPC **COOPERATIVE PATENT CLASSIFICATION**

G PHYSICS

(NOTES omitted)

INSTRUMENTS

G01 **MEASURING; TESTING** (NOTES omitted)

MEASURING ELECTRIC VARIABLES; MEASURING MAGNETIC VARIABLES G01R (indicating correct tuning of resonant circuits H03J 3/12)

NOTES

- 1. This subclass covers:
 - · measuring all kinds of electric or magnetic variables directly or by derivation from other electric or magnetic variables;
 - measuring all kinds of electric or magnetic properties of materials;
 - testing electric or magnetic devices, apparatus or networks, (e.g. discharge tubes, amplifiers) or measuring their characteristics:
 - indicating presence or sign of current or voltage;
 - NMR, EPR or other spin-effect apparatus, not specially adapted for a particular application;
 - equipment for generating signals to be used for carrying out such tests and measurements.
- 2. In this subclass, the following terms or expressions are used with the meanings indicated:
 - "measuring" includes investigating;
 - "instruments" or "measuring instruments" means electro-mechanical measuring mechanisms;
 - "arrangements for measuring" means apparatus, circuits, or methods for measuring;
- 3. Attention is drawn to the Notes following the title of class G01.
- 4. In this subclass, instruments or arrangements for measuring electric variables are classified in the following way:
 - Electromechanical instruments where the measured electric variables directly effect the indication of the measured value, including combined effects of two or more values, are classified in groups G01R 5/00 - G01R 11/00.
 - Details common to different types of the instruments covered by groups G01R 5/00 G01R 11/00 are classified in group G01R 1/00.
 - · Arrangements involving circuitry to obtain an indication of a measured value by deriving, calculating or otherwise processing electric variables, e.g. by comparison with another value, are classified in groups G01R 17/00 - G01R 29/00.
 - Details common to different types of arrangements covered by groups G01R 17/00 G01R 29/00 are classified in group G01R 15/00.
- 5. In this subclass, group G01R 17/00 takes precedence over groups G01R 19/00 G01R 31/00.

WARNING

In this subclass non-limiting references (in the sense of paragraph 39 of the Guide to the IPC) may still be displayed in the scheme.

1/00	Details of instruments or arrangements of the	1/0416	
	types included in groups <u>G01R 5/00</u> - <u>G01R 13/00</u>		
	and G01R 31/00 (constructional details particular to		
	{electromechanical} arrangements for measuring the		
	electric consumption G01R 11/02)	1/0425	
1/02	General constructional details	1/0433	
1/025	• • {concerning dedicated user interfaces, e.g. GUI,	1/0441	
	or dedicated keyboards (<u>G01R 31/31912</u> takes precedence)}	1/045	••••
1/04	• Housings; Supporting members; Arrangements of terminals	1/0458	• • • •
1/0408	• • • {Test fixtures or contact fields; Connectors or connecting adaptors; Test clips; Test	1/0466	• • • •
	sockets (<u>G01R 1/067</u> takes precedence; mass production testing systems <u>G01R 31/59</u> ; testing of connections <u>G01R 31/66</u> ; for testing printed circuit boards <u>G01R 31/2808</u>)}	1/0475	

1/0416	• • • • {Connectors, terminals (<u>G01R 1/0425</u> and <u>G01R 1/0433</u> take precedence; with measurement function for battery poles <u>G01R 31/364</u>)}
1/0425	• • • • {Test clips, e.g. for IC's}
1/0433	• • • • {Sockets for IC's or transistors}
1/0441	••••• {Details}
1/045	••••• {Sockets or component fixtures for RF or HF testing}
1/0458	••••• {related to environmental aspects, e.g. temperature}
1/0466	••••• {concerning contact pieces or mechanical details, e.g. hinges or cams; Shielding}
1/0475	••••• {for TAB IC's}

1/0483	• • • • {Sockets for un-leaded IC's having matrix
	type contact fields, e.g. BGA or PGA
	devices; Sockets for unpackaged, naked
	chips (for IC's with connecting points
	around the edges only <u>G01R 1/0433</u>)}
1/0491	• • • { for testing integrated circuits on wafers, e.g.
	wafer-level test cartridge}
1/06	• Measuring leads; Measuring probes
1/0 < 7	(<u>G01R 19/145</u> , <u>G01R 19/165</u> take precedence)
1/067	Measuring probes
1/06705	• • • {Apparatus for holding or moving single
	probes (for moving multiple probe heads or
1/06711	ICs under test <u>G01R 31/2886</u>)}
1/00/11	• • • {Probe needles; Cantilever beams; "Bump" contacts; Replaceable probe pins}
1/06716	• • • • {Elastic}
1/06722	{Spring-loaded}
1/06727	• • • • • {Spring-roaded}
1/00/27	
	WARNING
	This group is not complete pending
	a reorganisation; see also other
	subgroups of G01R 1/06711
1/06733	{Geometry aspects (G01R 1/06727 takes
	precedence)}
1/06738	••••• {related to tip portion}
1/06744	••••• {Microprobes, i.e. having dimensions as
	IC details }
1/0675	••••• {Needle-like}
1/06755	•••• {Material aspects}
1/06761	••••• {related to layers}
1/06766	• • • {Input circuits therefor}
1/06772	• • • • {High frequency probes}
1/06777	• • • {High voltage probes}
1/06783	• • • {containing liquids}
1/06788	• • • {Hand-held or hand-manipulated probes,
	e.g. for oscilloscopes or for portable test
	instruments (end pieces terminating in a
	probe <u>H01R 11/18</u>)}
1/06794	• • • • {Devices for sensing when probes are
	in contact, or in position to contact, with measured object}
1/07	Non contact-making probes
1/071	{containing electro-optic elements}
1/072	{containing electro-optic elements}
1/072	Multiple probes
1/07307	••••• {with individual probe elements, e.g.
1,01301	needles, cantilever beams or bump
	contacts, fixed in relation to each other,
	e.g. bed of nails fixture or probe card}
1/07314	••••• {the body of the probe being
	perpendicular to test object, e.g. bed of
	nails or probe with bump contacts on a
	rigid support (on an elastic support, e.g.
1/07001	a film, <u>G01R 1/0735</u>)}
1/07321	{the probes being of different
1/07220	lengths}
1/07328	{for testing printed circuit boards}
1/07335	for double-sided contacting or for testing boards with surface-
	mounted devices (SMD's)}
1/07342	• • • • • {the body of the probe being at an angle
1,01372	other than perpendicular to test object,
	e.g. probe card}

1/0735	••••• {arranged on a flexible frame or film}
1/07357	••••• {with flexible bodies, e.g. buckling
	beams}
1/07364	••••• {with provisions for altering position,
	number or connection of probe tips;
	Adapting to differences in pitch}
1/07371	••••• {using an intermediate card or back
	card with apertures through which the
	probes pass}
1/07378	• • • • • • {using an intermediate adapter, e.g.
	space transformers (G01R 1/07371
1/07205	takes precedence)}
1/07385	{using switching of signals between probe tips and test bed, i.e. the
	standard contact matrix which in its
	turn connects to the tester}
1/07392	••••• {manipulating each probe element or tip
	individually}
1/08	• • Pointers; Scales; Scale illumination
1/10	Arrangements of bearings
1/12	• • • of strip or wire bearings
1/14	• • Braking arrangements; Damping arrangements
1/16	Magnets
1/18	Screening arrangements against electric or
	magnetic fields, e.g. against earth's field
1/20	. Modifications of basic electric elements for use
	in electric measuring instruments; Structural
	combinations of such elements with such instruments
1/203	• {Resistors used for electric measuring, e.g.
1/205	decade resistors standards, resistors for
	comparators, series resistors, shunts (resistors
	in general <u>H01C</u> ; microwave or radiowave
	terminations H01P 1/26; coupling devices
	<u>H01R</u>)}
1/206	• • {Switches for connection of measuring
	instruments or electric motors to measuring loads
	(switches in general <u>H01H</u>)}
1/22	• • Tong testers acting as secondary windings of
1/24	current transformers
1/24	• Transmission-line, e.g. waveguide, measuring sections, e.g. slotted section
1/26	• • • with linear movement of probe
1/28	 Provision in measuring instruments for reference
1/20	values, e.g. standard voltage, standard waveform
1/30	• Structural combination of electric measuring
	instruments with basic electronic circuits, e.g. with
	amplifier
1/36	. Overload-protection arrangements or circuits for
	electric measuring instruments
1/38	Arrangements for altering the indicating
	characteristic, e.g. by modifying the air gap
1/40	• Modifications of instruments to indicate the
	maximum or the minimum value reached in a time
1/40	interval, e.g. by maximum indicator pointer
1/42 1/44	thermally operatedModifications of instruments for temperature
1/44	compensation
	-
3/00	Apparatus or processes specially adapted for
	the manufacture {or maintenance} of measuring instruments {, e.g. of probe tips}
5/00	Instruments for converting a single current or a

(00 Instruments for converting a single current or a single voltage into a mechanical displacement

5/02	• Moving-coil instruments
5/04	• • with magnet external to the coil
5/06	• • with core magnet
5/08	 specially adapted for wide angle deflection; with eccentrically-pivoted moving coil
5/10	String galvanometers
5/12	. Loop galvanometers
5/14	• Moving-iron instruments
5/16	• • with pivoting magnet
5/18	• • with pivoting soft iron, e.g. needle galvanometer
5/20	• Induction instruments, e.g. Ferraris instruments
5/22	• Thermoelectric instruments
5/24	• operated by elongation of a strip or wire or by expansion of a gas or fluid
5/26	• • operated by deformation of a bimetallic element
5/28	Electrostatic instruments
5/30	. Leaf electrometers
5/32	Wire electrometers; Needle electrometers
5/34	Quadrant electrometers
7/00	Instruments capable of converting two or more
//00	currents or voltages into a single mechanical displacement (<u>G01R 9/00</u> takes precedence)
7/02	 for forming a sum or a difference
7/02	 for forming a quotient (for measuring resistance
7/06	<u>G01R 27/08</u>) • moving-iron type
1/00	NOTE
	This group <u>covers</u> all crossed-coil meters, i.e. logometers having a magnetic rotor
7/08	• • moving-coil type, e.g. crossed-coil type
7/10	having more than two moving coils
7/12	• for forming product
7/14	moving-iron type
7/16	• having both fixed and moving coils, i.e. dynamometers
7/18	• • • with iron core magnetically coupling fixed and moving coils
9/00	Instruments employing mechanical resonance
9/02	• Vibration galvanometers, e.g. for measuring current
9/02 9/04	 using vibrating reeds, e.g. for measuring frequency
9/04 9/06	. magnetically driven
9/08	piezoelectrically driven
11/00	Electromechanical arrangements for measuring
11/00	time integral of electric power or current, e.g. of
	consumption (monitoring electric consumption of
	electrically-propelled vehicles <u>B60L 3/00</u>)
	NOTES
	1. Groups <u>G01R 11/48</u> - <u>G01R 11/56</u> take precedence
	over groups <u>G01R 11/30</u> - <u>G01R 11/46</u> .
	{This Note corresponds to IPC Note (1) relating to G01R 11/30 - G01R 11/46.}
	2. For the definition of "arrangement" see Note (2)
	under <u>G01R</u>
11/02	Constructional details
11/04	• • Housings; Supporting racks; Arrangements of
	terminals
11/06	Magnetic circuits of induction meters
11/067	Coils therefor

11/073	• • • Armatures therefor
11/09	Disc armatures
11/10	Braking magnets; Damping arrangements
11/12 11/14	Arrangements of bearingswith magnetic relief
11/14	 with magnetic relief Adaptations of counters to electricity meters
11/17	Compensating for errors; Adjusting or regulating
11/1/	means therefor
11/18	Compensating for variations in ambient conditions
11/185	Temperature compensation
11/19	Compensating for errors caused by disturbing torque, e.g. rotating-field errors of polyphase meters
11/20	Compensating for phase errors in induction meters
11/21	• • Compensating for errors caused by damping effects of the current, e.g. adjustment in the overload range
11/22	• • Adjusting torque, e.g. adjusting starting torque, adjusting of polyphase meters for obtaining equal torques
11/23	Compensating for errors caused by friction, e.g. adjustment in the light load range
11/24	• Arrangements for avoiding or indicating fraudulent use
11/25	Arrangements for indicating or signalling faults
11/30	Dynamo-electric motor meters
11/32	Watt-hour meters
11/34	Ampere-hour meters
11/36	• Induction meters, e.g. Ferraris meters
11/38	• • for single-phase operation
11/40	• • for polyphase operation
11/42	Circuitry therefor
11/46	• Electrically-operated clockwork meters; Oscillatory meters; Pendulum meters
11/465	• {Oscillatory meters}
11/48	• Meters specially adapted for measuring real or reactive components; Meters specially adapted for measuring apparent energy
11/50	• • for measuring real component
11/52	for measuring reactive component
11/54	• for measuring simultaneously at least two of the following three variables: real component, reactive component, apparent energy
11/56	Special tariff meters
11/57	• Multi-rate meters ($\underline{G01R \ 11/63}$ takes precedence)
11/58	• • Tariff-switching devices therefor
11/60	• Subtraction meters; Meters measuring maximum or minimum load hours
11/63	• Over-consumption meters, e.g. measuring consumption while a predetermined level of power is exceeded
11/64	• Maximum meters, e.g. tariff for a period is based on maximum demand within that period
11/66	Circuitry
13/00	Arrangements for displaying electric variables or waveforms
13/02	 for displaying measured electric variables in digital form
13/0209	• • {in numerical form}
13/0218	• • {Circuits therefor}

13/0227	• • • {Controlling the intensity or colour of the
	display }
13/0236	• • • {for presentation of more than one variable}
13/0245	• • • {for inserting reference markers}
13/0254	• • { for triggering, synchronisation }
13/0263	• • • • {for non-recurrent functions, e.g. transients}
13/0272	{for sampling}
13/0281	• • {using electro-optic elements}
13/029	• • {Software therefor}
13/04	• for producing permanent records
13/06	• • Modifications for recording transient
	disturbances, e.g. by starting or accelerating a
	recording medium
13/08	• Electromechanical recording systems using a
	mechanical direct-writing method
13/10	• • • with intermittent recording by representing
	the variable by the length of a stroke or by the
	position of a dot
13/12	• Chemical recording, e.g. clydonographs
10/12	(<u>G01R 13/14</u> takes precedence)
13/14	• Recording on a light-sensitive material
13/14	Recording on a magnetic medium
13/18	using boundary displacement
13/18	
	• Cathode-ray oscilloscopes
13/202	• {Non-electric appliances, e.g. scales, masks
	(luminescent screens for CRT provided with
	permanent marks or references <u>H01J 29/34;</u> optical or photographic arrangements combined
	with CRT vessels <u>H01J 29/89</u>)}
13/204	• {Using means for generating permanent
13/204	registrations, e.g. photographs (optical or
	photographic arrangements combined with CRT
	vessel <u>H01J 29/89</u>)}
13/206	• {Arrangements for obtaining a 3- dimensional
13/200	representation (stereoscopic T.V. <u>H04N 13/00</u>)}
13/208	• {Arrangements for measuring with C.R.
15/200	oscilloscopes, e.g. vectorscope}
13/22	Circuits therefor
13/225	 {particularly adapted for storage oscilloscopes}
13/24	Time-base deflection circuits
	 for generating more than one, not
13/245	overlapping time-intervals on the screen }
12/26	
13/26	Circuits for controlling the intensity of the
12/20	electron beam {or the colour of the display}
13/28	Circuits for simultaneous or sequential presentation of more than one variable
12/20	-
13/30	Circuits for inserting reference markers, e.g. for timing for calibrating for frequency marking
12/205	timing, for calibrating, for frequency marking
13/305	{for time marking}
13/32	Circuits for displaying non-recurrent functions
	such as transients; Circuits for triggering; Circuits for synchronication; Circuits for time
	Circuits for synchronisation; Circuits for time-
12/225	base expansion
13/325	• • • {for displaying non-recurrent functions such as transients}
12/24	,
13/34	Circuits for representing a single waveform by
12/240	sampling, e.g. for very high frequencies
13/342	{for displaying periodic H.F. signals
12/245	(<u>G01R 13/345</u> takes precedence)}
13/345	{ for displaying sampled signals by using
	digital processors by intermediate A.D. and
	D.A. convertors (control circuits for CRT
12/247	indicators)}
13/347	{using electro-optic elements}

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more than one variable
erting reference markers, e.g. for
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playing non-recurrent functions
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chronisation; Circuits for time-
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or very high frequencies
ng periodic H.F. signals
5 takes precedence)}
ng sampled signals by using
sors by intermediate A.D. and
ors (control circuits for CRT
o-optic elements}

13/36	• using length of glow discharge, e.g. glowlight oscilloscopes
13/38	 using the steady or oscillatory displacement of a light beam by an electromechanical measuring system
13/40	 using modulation of a light beam otherwise than by mechanical displacement, e.g. by Kerr effect {(visual indication of correct tuning H03J 3/14)}
13/401	 ((i) and interaction of concertaining <u>receipting</u>) (for continuous analogue, or simulated analogue, display}
13/402	 • {using active, i.e. light-emitting display devices, e.g. electroluminescent display (<u>G01R 13/36</u> and <u>G01R 13/42</u> take precedence)}
13/403	 • {using passive display devices, e.g. liquid crystal display or Kerr effect display devices}
13/404	 (for discontinuous display, i.e. display of discrete values (analogue/digital conversion <u>H03M 1/00</u>)
13/405	 {using a plurality of active, i.e. light emitting, e.g. electro-luminescent elements, i.e. bar graphs}
13/406	• • • {representing measured value by a dot or a single line (<u>G01R 13/408</u> takes precedence)}
13/407	• • {using a plurality of passive display elements, e.g. liquid crystal or Kerr-effect display elements (<u>G01R 13/408</u> takes precedence)}
13/408	• • {Two or three dimensional representation of measured values}
13/42	• Instruments using length of spark discharge, e.g. by measuring maximum separation of electrodes to produce spark
15/00	Details of measuring arrangements of the types
15/00	provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u> ,
15/002	provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u> , <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u>
15/002	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters}
	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear}
15/002 15/005 15/007	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression}
15/002 15/005 15/007 15/04	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers
15/002 15/005 15/007 15/04 15/06	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer
15/002 15/005 15/007 15/04 15/06 15/08	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range
15/002 15/005 15/007 15/04 15/06 15/08 15/09	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range Autoranging circuits
15/002 15/005 15/007 15/04 15/06 15/08	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range Autoranging circuits Circuits for multi-testers {, i.e. multimeters}, e.g.
15/002 15/005 15/007 15/04 15/06 15/08 15/09	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range Autoranging circuits Circuits for multi-testers {, i.e. multimeters}, e.g. for measuring voltage, current, or impedance at will
15/002 15/005 15/007 15/04 15/06 15/08 15/09 15/12	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range Autoranging circuits Circuits for multi-testers {, i.e. multimeters}, e.g.
15/002 15/005 15/007 15/04 15/06 15/08 15/09 15/12 15/125	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range Autoranging circuits Circuits for multi-testers {, i.e. multimeters}, e.g. for measuring voltage, current, or impedance at will {for digital multimeters}
15/002 15/005 15/007 15/04 15/06 15/08 15/09 15/12 15/125	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range Autoranging circuits Circuits for multi-testers {, i.e. multimeters}, e.g. for measuring voltage, current, or impedance at will {for digital multimeters} Adaptations providing voltage or current isolation,
15/002 15/005 15/007 15/04 15/06 15/08 15/09 15/12 15/125 15/14	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range Autoranging circuits Circuits for multi-testers {, i.e. multimeters}, e.g. for measuring voltage, current, or impedance at will {for digital multimeters} Adaptations providing voltage or current isolation, e.g. for high-voltage or high-current networks {Arrangements for simultaneous measurements of several parameters employing techniques covered
15/002 15/005 15/007 15/04 15/06 15/08 15/09 15/12 15/125 15/14 15/142	 provided for in groups <u>G01R 17/00</u> - <u>G01R 29/00</u>, <u>G01R 33/00</u> - <u>G01R 33/26</u> or <u>G01R 35/00</u> {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range Autoranging circuits Circuits for multi-testers {, i.e. multimeters}, e.g. for measuring voltage, current, or impedance at will {for digital multimeters} Adaptations providing voltage or current isolation, e.g. for high-voltage or high-current networks {Arrangements for simultaneous measurements of several parameters employing techniques covered by groups <u>G01R 15/14</u> - <u>G01R 15/26</u>} {Measuring arrangements for voltage not covered
15/002 15/005 15/007 15/04 15/06 15/08 15/09 15/12 15/125 15/14 15/142	 provided for in groups G01R 17/00 - G01R 29/00, G01R 33/00 - G01R 33/26 or G01R 35/00 {Switches for altering the measuring range or for multitesters} {Circuits for altering the indicating characteristic, e.g. making it non-linear} {by zero-suppression} Voltage dividers having reactive components, e.g. capacitive transformer Circuits for altering the measuring range Autoranging circuits Circuits for multi-testers {, i.e. multimeters}, e.g. for measuring voltage, current, or impedance at will {for digital multimeters} Adaptations providing voltage or current isolation, e.g. for high-voltage or high-current networks {Arrangements for simultaneous measurements of several parameters employing techniques covered by groups G01R 15/14 - G01R 15/26} {Measuring arrangements for voltage not covered by other subgroups of G01R 15/14} {Measuring arrangements for current not covered by other subgroups of G01R 15/14, e.g. using current dividers, shunts, or measuring a voltage drop (if no voltage isolation is involved

15/165	• • { measuring electrostatic potential, e.g. with electrostatic voltmeters or electrometers, when the design of the sensor is essential	17/06 17/08	Automatic balancin in which a force measured value i
	(electrometers with passively moving electrodes <u>G01R 5/28;</u> measuring electrostatic	17/10	representing the • AC or DC measuring
	fields <u>G01R 29/12</u> ; measuring charge	17/10	 AC of DC measuring {for measuring imp
	<u>G01R 29/24;</u> measuring in circuits with high	17/12	• • using comparison of
15/18	 internal resistance <u>G01R 19/0023</u>)} using inductive devices, e.g. transformers 		differential current
15/181	• • {using coils without a magnetic core, e.g. Rogowski coils}	17/14	• with indication of r null indicator, e.g. p bridge (G01R 17/12
15/183	• • {using transformers with a magnetic core}		precedence)
15/185	• • • { with compensation or feedback windings or interacting coils, e.g. 0-flux sensors (using galvano-magnetic field sensors <u>G01R 15/20</u> ;	17/16	• with discharge tube in one or more arm using a difference a
	conversion of DC into AC using transductors G01R 19/20)}	17/18	• • with more than four
15/186	• • {using current transformers with a core	17/20	 AC or DC potentiome with indication of n
	consisting of two or more parts, e.g. clamp- on type (<u>G01R 15/142</u> - <u>G01R 15/16</u> take	17/22	null indicator
	precedence; tong testers $GOIR 1/22$)	19/00	Arrangements for mea
15/188	• • {comprising rotatable parts, e.g. moving coils (galvanometers <u>G01R 5/02</u> , <u>G01R 5/14</u>)}		voltages or for indicati (<u>G01R 5/00</u> takes preced
15/20	• • using galvano-magnetic devices, e.g. Hall-		bioelectric currents or v
	effect devices {, i.e. measuring a magnetic field via the interaction between a current and		<u>NOTE</u>
	a magnetic field, e.g. magneto resistive or Hall		Within groups G01R
	effect devices}		group <u>G01R 19/28</u> ta <u>G01R 19/18</u> - <u>G01R</u>
15/202	• • • {using Hall-effect devices (Hall elements in arrangements for measuring electrical power		over groups $G01R 19/18$
	<u>G01R 21/08</u>)}		<u>G01R 19/30</u> .
15/205	• • • {using magneto-resistance devices, e.g. field	19/0007	• {Frequency selective
15/207	plates}• {Constructional details independent of the type		measuring (measuring
15/207	of device used}		testing attenuation in <u>H04B 3/48;</u> monitorir
15/22	• • using light-emitting devices, e.g. LED,		systems <u>H04B 17/00</u>)
	optocouplers {(<u>G01R 31/31901</u> takes precedence)}	19/0015	• • {separating AC and
15/24	• using light-modulating devices	19/0023	• {Measuring currents of high internal resistant
15/241	• • {using electro-optical modulators, e.g. electro- absorption (probes containing electro-optic		circuits with high input amplifiers (electrostat
	elements <u>G01R 1/071</u>)}		measuring electrostat
15/242	• • • {based on the Pockels effect, i.e. linear electro-optic effect}		measuring electrostati amplifiers <u>per se H03</u>
15/243	• • • {based on the Kerr effect, i.e. quadratic	19/003	• {Measuring mean val
	electro-optic effect}		during a given time in
15/245	• • {using magneto-optical modulators, e.g. based on the Faraday or Cotton-Mouton effect}	19/0038	• {Circuits for compari for indicating the resu
15/246	• • • {based on the Faraday, i.e. linear magneto- optic, effect}		equal, different, great or pulse trains accord
15/247	• • {Details of the circuitry or	19/0046	• {characterised by a sp
	construction of devices covered by		covered by any other
15/248	<u>G01R 15/241</u> - <u>G01R 15/246</u> } {using a constant light source and electro-	19/0053	• {Noise discriminati Measuring transien
13/240	mechanically driven deflectors}		of individual pulses
15/26	 using modulation of waves other than light, e.g. radio or acoustic waves 		sampling <u>G01R 19/</u> <u>G01R 29/26</u>)}
17/00	Measuring arrangements involving comparison	19/0061	• • {Measuring current from electron multi
17/02	with a reference value, e.g. bridgeArrangements in which the value to be measured is	10/07	currents; Measuring
17/02	automatically compared with a reference value	19/0069 19/0076	 {measuring voltage {using thermionic voltage
17/04	• • in which the reference value is continuously or	19/0076 19/0084	 {using thermionic v {measuring voltage o
	periodically swept over the range of values to be measured		<u>G01R 19/00</u> take prec

17/06	• • Automatic balancing arrangements
17/08	in which a force or torque representing the
11/00	measured value is balanced by a force or torque representing the reference value
17/10	• AC or DC measuring bridges
17/105	• • {for measuring impedance or resistance}
17/12	• using comparison of currents, e.g. bridges with differential current output
17/14	• with indication of measured value by calibrated null indicator, e.g. percent bridge, tolerance bridge (<u>G01R 17/12</u> , <u>G01R 17/16</u> take precedence)
17/16	• with discharge tubes or semiconductor devices in one or more arms of the bridge, e.g. voltmeter using a difference amplifier
17/18	• • with more than four branches
17/20	• AC or DC potentiometric measuring arrangements
17/22	with indication of measured value by calibrated null indicator
19/00	Arrangements for measuring currents or
	voltages or for indicating presence or sign thereof
	(G01R 5/00 takes precedence; for measuring
	bioelectric currents or voltages <u>A61B 5/24</u>)
	NOTE
	Within groups <u>G01R 19/02</u> - <u>G01R 19/32</u> ,
	group $G01R 19/28$ takes precedence. Groups
	<u>G01R 19/18</u> - <u>G01R 19/257</u> take precedence
	over groups <u>G01R 19/02</u> - <u>G01R 19/17</u> and <u>G01R 19/30</u> .
19/0007	• {Frequency selective voltage or current level
19/0007	measuring (measuring frequency <u>G01R 23/00;</u>
	testing attenuation in line transmission systems
	<u>H04B 3/48;</u> monitoring testing in transmission
	systems <u>H04B 17/00</u>)}
19/0015	• { separating AC and DC}
19/0013	• {Separating AC and DC} • {Measuring currents or voltages from sources with
19/0025	high internal resistance by means of measuring
	circuits with high input impedance, e.g. OP-
	amplifiers (electrostatic instruments <u>G01R 5/28;</u>
	measuring electrostatic potential <u>G01R 5/28</u> ,
	measuring electrostatic fields <u>G01R 29/12;</u>
	amplifiers <u>per se H03F</u>)}
19/003	• {Measuring mean values of current or voltage
19/003	during a given time interval }
19/0038	• {Circuits for comparing several input signals and
17/0050	for indicating the result of this comparison, e.g.
	equal, different, greater, smaller (comparing pulses
	or pulse trains according to amplitude)}
19/0046	• {characterised by a specific application or detail not
	covered by any other subgroup of $GO1R 19/00$ }
19/0053	• • {Noise discrimination; Analog sampling;
	Measuring transients (measuring characteristics
	of individual pulses G01R 29/02; digital
	sampling <u>G01R 19/2509;</u> measuring noise figure
	G01R 29/26)
19/0061	• • {Measuring currents of particle-beams, currents
	from electron multipliers, photocurrents, ion
	currents; Measuring in plasmas}
19/0069	• {measuring voltage or current standards}
19/0076	 • {using thermionic valves}
19/0076	 {using inclinione varies} {measuring voltage only (all subgroups of
12/0004	$\frac{G01R \ 19/00}{C} \text{ take precedence} $

19/0092	• {measuring current only (all subgroups of <u>G01R 19/00</u> take precedence)}	
19/02	• Measuring effective values, i.e. root-mean-square values	
19/03	• • using thermoconverters	
19/04	• Measuring peak values {or amplitude or envelope} of ac or of pulses	
19/06	• Measuring real component; Measuring reactive component	
19/08	• Measuring current density	
19/10	• Measuring sum, difference or ratio	
19/12	• Measuring rate of change	
19/14	• Indicating direction of current; Indicating polarity of voltage	
19/145	• Indicating the presence of current or voltage	
19/15	• Indicating the presence of current	
19/155	• Indicating the presence of voltage	
19/165	• Indicating that current or voltage is either above or	
	below a predetermined value or within or outside a predetermined range of values	
19/16504	• {characterised by the components employed}	
19/16509	• • {using electromagnetic relays, e.g. reed relay (magnetically driven reeds <u>G01R 9/06</u>)}	
19/16514	• • {using electronic tubes}	
19/16519	• • • {using FET's}	
19/16523	• • {using diodes, e.g. Zener diodes}	
19/16528	• • {using digital techniques or performing arithmetic	
	operations (using digital techniques to measure a voltage or a current, see G01R 19/25)}	
19/16533	• {characterised by the application}	
19/16538	• • • {in AC or DC supplies (<u>G01R 19/16519</u> and	
	<u>G01R 19/16528</u> take precedence)}	
19/16542	•••• { for batteries (charge condition monitoring in <u>G01R 31/36</u>) }	
19/16547	•••• {voltage or current in AC supplies (switching for protection <u>H02H</u> ; circuits for emergency	
	power supply H02J 9/00)}	
19/16552	• • • {in I.C. power supplies}	
19/16557	{Logic probes, i.e. circuits indicating logic	
	state (high, low, O); (modifications of	
	electronic switches or gates for indicating state	
19/16561	 of switch <u>H03K 17/18</u>) {in hand-held circuit testers (see also 	
19/10301	$\frac{G01R 19/155}{3}$	
19/16566	• {Circuits and arrangements for comparing	
17/10500	voltage or current with one or several thresholds	
	and for indicating the result not covered by	
	subgroups G01R 19/16504, G01R 19/16528,	
	<u>G01R 19/16533</u> }	
19/16571	• • • {comparing AC or DC current with one	
	threshold, e.g. load current, over-current,	
	surge current or fault current (<u>G01R 19/16514</u> ,	
	<u>G01R 19/16519</u> , <u>G01R 19/16528</u> ,	
	<u>G01R 19/16533</u> , <u>G01R 19/1659</u> take	
	precedence; measuring currents by using elements sensitive to the magnetic field	
	generated <u>G01R 15/14</u> ; measuring earth	
	resistance $\underline{G01R}$ 27/18; testing for leakage	
	or short circuits in electrical apparatus	
	<u>G01R 31/52</u>)}	
19/16576	• • • {comparing DC or AC voltage with one	
	threshold (<u>G01R 19/16514</u> , <u>G01R 19/16519</u> ,	
	<u>G01R 19/16528</u> , <u>G01R 19/16533</u> and	
	<u>G01R 19/1659</u> take precedence)}	

10/1650	
19/1658	• • • {AC voltage or recurrent signals}
19/16585	The second
	applications where timing or duration is of
	importance (<u>G01R 19/16519</u> , <u>G01R 19/16538</u> and <u>G01R 19/16595</u> take precedence; for pulse
	· · · · ·
	duration and rise time, <u>see G01R 29/02</u> and subgroups)}
19/1659	• • {to indicate that the value is within or
19/1039	outside a predetermined range of values
	(window) (<u>G01R 19/16514</u> , <u>G01R 19/16519</u> ,
	GOIR 19/16528 and $GOIR 19/16533$ take
	precedence)}
19/16595	• • • {with multi level indication (<u>G01R 19/16519</u>
	and G01R 19/16533 take precedence)}
19/17	• giving an indication of the number of times this
	occurs {, i.e. multi-channel analysers}
19/175	. Indicating the instants of passage of current or
	voltage through a given value, e.g. passage through
	zero
19/18	• using conversion of DC into AC, e.g. with choppers
19/20	• • using transductors {, i.e. a magnetic core
	transducer the saturation of which is cyclically
	reversed by an AC source on the secondary side}
19/22	• using conversion of ac into dc
19/225	• • {by means of thermocouples or other heat
2010/24	sensitive elements }
2019/24	• {using thermocouples}
19/25	• using digital measurement techniques
19/2503	• {for measuring voltage only, e.g. digital volt meters (DVM's) (<u>G01R 19/2506</u> - <u>G01R 19/257</u>
	take precedence)}
19/2506	Arrangements for conditioning or analysing
19/2000	measured signals, e.g. for indicating peak
	values (<u>G01R 19/003</u> takes precedence); Details
	concerning sampling, digitizing or waveform
	capturing (displaying waveforms G01R 13/00;
	analog sampling <u>G01R 19/0053</u>)}
19/2509	• • • {Details concerning sampling, digitizing or
	waveform capturing}
19/2513	• • {Arrangements for monitoring electric power
	systems, e.g. power lines or loads; Logging}
19/2516	• • {Modular arrangements for computer based
	systems; using personal computers (PC's), e.g.
10/252	"virtual instruments"}
19/252	• using analogue/digital converters of the type with conversion of voltage or current into frequency
	and measuring of this frequency
19/255	• using analogue/digital converters of the type
197200	with counting of pulses during a period of time
	proportional to voltage or current, delivered by a
	pulse generator with fixed frequency
19/257	using analogue/digital converters of the type with
	comparison of different reference values with the
	value of voltage or current, e.g. using step-by-step
	method
19/28	• adapted for measuring in circuits having distributed
10/20	constants
19/30	• Measuring the maximum or the minimum value
	of current or voltage reached in a time interval (G01R 19/04 takes precedence)
19/32	Compensating for temperature change
21/00	Arrangements for measuring electric power or
	power factor (<u>G01R 7/12</u> takes precedence)

21/001	• {Measuring real or reactive component; Measuring apparent energy (<u>G01R 21/01</u> , <u>G01R 21/02</u> , <u>G01R 21/08</u> , <u>G01R 21/10</u> and <u>G01R 21/127</u> take
21/002	<pre>precedence)} {Measuring real component}</pre>
21/002	 {Measuring reactive component} {Measuring reactive component}
21/005	• {Measuring apparent power}
21/006	• {Measuring power factor}
21/007	 {Adapted for special tariff measuring (<u>G01R 21/01</u>, <u>G01R 21/02</u>, <u>G01R 21/08</u>, <u>G01R 21/10</u>, <u>G01R 21/1278</u> and <u>G01R 21/1333</u> take precedence)}
21/008	• {Measuring maximum demand}
21/008	 in circuits having distributed constants
21/01	(<u>G01R 21/04</u> , <u>G01R 21/07</u> , <u>G01R 21/09</u> , <u>G01R 21/12</u> take precedence)
21/02	• by thermal methods {, e.g. calorimetric}
21/02	 by itermat methods {, e.g. calorimetric} in circuits having distributed constants
21/04	 by measuring current and voltage
21/00	(G01R 21/08 - G01R 21/133) take precedence)
21/07	• in circuits having distributed constants
_1/0/	(<u>G01R 21/09</u> takes precedence)
21/08	• by using galvanomagnetic-effect devices, e.g. Hall-
	effect devices
21/09	• • in circuits having distributed constants
21/10	• by using square-law characteristics of circuit
	elements, e.g. diodes, to measure power absorbed
	by loads of known impedance (G01R 21/02 takes
	precedence)
21/12	• • in circuits having distributed constants
21/127	• by using pulse modulation (G01R 21/133 takes
	precedence)
21/1271	• • {Measuring real or reactive component, measuring apparent energy}
21/1273	• • {Measuring real component}
21/1275	• • {Measuring reactive component}
21/1276	• • {Measuring apparent energy}
21/1278	• {Adapted for special tariff measuring}
21/133	• by using digital technique
21/1331	 . {Measuring real or reactive component,
21/1001	measuring apparent energy}
21/1333	• {adapted for special tariff measuring}
21/1335	• • • {Tariff switching circuits}
21/1336	• • {Measuring overconsumption}
21/1338	• • {Measuring maximum demand}
21/14	. Compensating for temperature change
22/00	
	Arrangements for measuring time integral of electric power or current, e.g. electricity meters
	electric power or current, e.g. electricity meters <u>NOTE</u>
	electric power or current, e.g. electricity meters <u>NOTE</u> An arrangement for measuring time integral of
	electric power or current, e.g. electricity meters <u>NOTE</u> An arrangement for measuring time integral of electric power is classified in group <u>G01R 21/00</u>
	electric power or current, e.g. electricity meters <u>NOTE</u> An arrangement for measuring time integral of electric power is classified in group <u>G01R 21/00</u> if the essential characteristic is the measuring of
	electric power or current, e.g. electricity meters <u>NOTE</u> An arrangement for measuring time integral of electric power is classified in group <u>G01R 21/00</u> if the essential characteristic is the measuring of electric power.
22/02	 electric power or current, e.g. electricity meters <u>NOTE</u> An arrangement for measuring time integral of electric power is classified in group G01R 21/00 if the essential characteristic is the measuring of electric power. by electrolytic methods
22/04	 electric power or current, e.g. electricity meters <u>NOTE</u> An arrangement for measuring time integral of electric power is classified in group <u>G01R 21/00</u> if the essential characteristic is the measuring of electric power. by electrolytic methods by calorimetric methods
22/04 22/06	 electric power or current, e.g. electricity meters <u>NOTE</u> An arrangement for measuring time integral of electric power is classified in group <u>G01R 21/00</u> if the essential characteristic is the measuring of electric power. by electrolytic methods by calorimetric methods by electronic methods
22/04 22/06 22/061	 electric power or current, e.g. electricity meters <u>NOTE</u> An arrangement for measuring time integral of electric power is classified in group <u>G01R 21/00</u> if the essential characteristic is the measuring of electric power. by electrolytic methods by calorimetric methods by electronic methods {Details of electronic electricity meters}
22/04 22/06	 electric power or current, e.g. electricity meters NOTE An arrangement for measuring time integral of electric power is classified in group G01R 21/00 if the essential characteristic is the measuring of electric power. by electrolytic methods by calorimetric methods by electronic methods {Details of electronic electricity meters} {related to remote communication}
22/04 22/06 22/061	 electric power or current, e.g. electricity meters NOTE An arrangement for measuring time integral of electric power is classified in group GOIR 21/00 if the essential characteristic is the measuring of electric power. by electrolytic methods by electronic methods by electronic methods . {Details of electronic electricity meters} . {related to remote communication} . {related to mechanical aspects}
22/04 22/06 22/061 22/063	 electric power or current, e.g. electricity meters NOTE An arrangement for measuring time integral of electric power is classified in group G01R 21/00 if the essential characteristic is the measuring of electric power. by electrolytic methods by calorimetric methods by electronic methods {Details of electronic electricity meters} {related to remote communication}

22/068	• • • {Arrangements for indicating or signaling faults}
22/08 22/10	using analogue techniquesusing digital techniques
23/00	Arrangements for measuring frequencies; Arrangements for analysing frequency spectra
23/005	• {Circuits for comparing several input signals and for indicating the result of this comparison, e.g. equal, different, greater, smaller (comparing phase or frequency of 2 mutually independent oscillations in demodulators)}
23/02	• Arrangements for measuring frequency, e.g. pulse repetition rate; Arrangements for measuring period of current or voltage
23/04	• adapted for measuring in circuits having distributed constants
23/06	• • by converting frequency into an amplitude of current or voltage
23/07	• • • using response of circuits tuned on resonance, e.g. grid-drip meter
23/08	using response of circuits tuned off resonance
23/09	 using analogue integrators, e.g. capacitors establishing a mean value by balance of input signals and defined discharge signals or leakage
23/10	 by converting frequency into a train of pulses, which are then counted {, i.e. converting the signal into a square wave}
23/12	• • by converting frequency into phase shift
23/14	• • by heterodyning; by beat-frequency comparison
23/145	• • • {by heterodyning or by beat-frequency comparison with the harmonic of an oscillator}
23/15	 Indicating that frequency of pulses is either above or below a predetermined value or within or outside a predetermined range of values, by making use of non-linear or digital elements {(indicating that pulse width is above or below a certain limit)}
23/155	• • • {giving an indication of the number of times this occurs, i.e. multi-channel analysers (for pulse characteristics)}
23/16	Spectrum analysis; Fourier analysis
23/163	adapted for measuring in circuits having distributed constants
23/165	• using filters
23/167 23/17	• • • with digital filters
23/17	with optical {or acoustical} auxiliary devicesWobbulating devices similar to swept panoramic
	receivers
23/175	• by delay means, e.g. tapped delay lines
23/177 23/18	Analysis of very low frequencieswith provision for recording frequency spectrum
23/18	Measurement of non-linear distortion
25/00	Arrangements for measuring phase angle between a voltage and a current or between voltages or currents
25/005	• {Circuits for comparing several input signals and for indicating the result of this comparison, e.g. equal, different, greater, smaller, or for passing one of the input signals as output signal}
25/02	• in circuits having distributed constants
25/04	• involving adjustment of a phase shifter to produce a predetermined phase difference, e.g. zero difference

25/06	• employing quotient instrument
25/08	 by counting of standard pulses
27/00	Arrangements for measuring resistance, reactance, impedance, or electric characteristics derived therefrom
27/02	 Measuring real or complex resistance, reactance, impedance, or other two-pole characteristics derived therefrom, e.g. time constant (by measuring phase angle only <u>G01R 25/00</u>)
	<u>NOTE</u>
	Groups <u>G01R 27/02</u> - <u>G01R 27/22</u> cover variables that directly or indirectly can be measured over two poles of a component or a Thevenin two-pole equivalent. Subgroup <u>G01R 27/26</u> also covers other techniques, e.g. using electro magnetic waves or network analyzers
27/025	• • {Measuring very high resistances, e.g. isolation resistances, i.e. megohm-meters}
27/04	 in circuits having distributed constants {, e.g. having very long conductors or involving high frequencies}
27/06	Measuring reflection coefficients; Measuring standing-wave ratio
27/08	Measuring resistance by measuring both voltage and current
27/10	• • using two-coil or crossed-coil instruments forming quotient
27/12	• • • • using hand generators, e.g. meggers
27/14	• Measuring resistance by measuring current or voltage obtained from a reference source (<u>G01R 27/16</u> , <u>G01R 27/20</u> , <u>G01R 27/22</u> take precedence)
27/16	• Measuring impedance of element or network through which a current is passing from another
27/18	 source, e.g. cable, power line Measuring resistance to earth {, i.e. line to ground}
27/20	 Measuring earth resistance; Measuring contact resistance, {e.g.} of earth connections, e.g. plates
27/205	{Measuring contact resistance of connections, e.g. of earth connections}
27/22	• • Measuring resistance of fluids
27/26	• Measuring inductance or capacitance; Measuring quality factor, e.g. by using the resonance method; Measuring loss factor; Measuring dielectric constants {; Measuring impedance or related variables}
27/2605	 . {Measuring capacitance (capacitive sensors G01D 5/24)}
27/2611	• • {Measuring inductance}
27/2617	• • • {Measuring dielectric properties, e.g. constants (testing dielectric strength <u>G01R 31/12;</u> detecting insulation faults <u>G01R 31/52;</u> <u>G01R 27/2688</u> takes precedence)}
27/2623	 {Measuring-systems or electronic circuits (<u>G01R 27/2635</u>, <u>G01R 27/2682</u> take precedence)}
27/2629	• • • • {Bridge circuits (bridges for measuring loss angle <u>G01R 27/2694</u>)}
27/2635	•••• {Sample holders, electrodes or excitation arrangements, e.g. sensors or measuring cells}

27/2641	•••• {of plate type, i.e. with the sample sandwiched in the middle}
27/2647	• • • • {of coaxial or concentric type, e.g. with the sample in a coaxial line}
27/2652	••••• {open-ended type, e.g. abutting against the sample }
27/2658	••••• {Cavities, resonators, free space arrangements, reflexion or interference arrangements (<u>G01R 27/2647</u> takes precedence; optical methods
27/2664	G01R 27/2682)} {Transmission line, wave guide (closed or open-ended) or strip - or microstrip line arrangements}
27/267	•••• {Coils or antennae arrangements, e.g. coils surrounding the sample or transmitter/ receiver antennae}
27/2676	• • • • • {Probes}
27/2682	• • • { using optical methods or electron beams }
27/2688	• • • {Measuring quality factor or dielectric loss, e.g. loss angle, or power factor (power factor related to power measurements <u>G01R 21/006;</u>
27/2/04	testing capacitors <u>G01R 31/016</u>)}
27/2694	• • • {Measuring dielectric loss, e.g. loss angle, loss factor or power factor}
27/28	• Measuring attenuation, gain, phase shift or derived characteristics of electric four pole networks, i.e. two-port networks; Measuring transient response (in line transmission systems H04B 3/46)
27/30	• with provision for recording characteristics, e.g. by plotting Nyquist diagram
27/32	 in circuits having distributed constants {, e.g. having very long conductors or involving high frequencies}
20/00	· · · · · · · · · · · · · · · · · · ·
29/00	Arrangements for measuring or indicating electric quantities not covered by groups <u>G01R 19/00</u> - <u>G01R 27/00</u>
29/02	• Measuring characteristics of individual pulses, e.g. deviation from pulse flatness, rise time or duration
29/023	• • {Measuring pulse width}
29/027	• Indicating that a pulse characteristic is either above or below a predetermined value or within or beyond a predetermined range of values
29/0273	 { the pulse characteristic being duration, i.e. width (indicating that frequency of pulses is above or below a certain limit)}
29/0276	• • • {the pulse characteristic being rise time (measuring rate of change <u>G01R 19/12</u>)}
	(incusting face of change <u>Gork 17/12</u>)
29/033	 giving an indication of the number of times this occurs {, i.e. multi-channel analysers (the characteristic being frequency)}
29/04	 giving an indication of the number of times this occurs {, i.e. multi-channel analysers (the characteristic being frequency)} Measuring form factor, i.e. quotient of root-mean-square value and arithmetic mean of instantaneous value; Measuring peak factor, i.e. quotient of maximum value and root-mean-square value
	 giving an indication of the number of times this occurs {, i.e. multi-channel analysers (the characteristic being frequency)} Measuring form factor, i.e. quotient of root-mean-square value and arithmetic mean of instantaneous value; Measuring peak factor, i.e. quotient of maximum value and root-mean-square value Measuring depth of modulation
29/04	 giving an indication of the number of times this occurs {, i.e. multi-channel analysers (the characteristic being frequency)} Measuring form factor, i.e. quotient of root-mean-square value and arithmetic mean of instantaneous value; Measuring peak factor, i.e. quotient of maximum value and root-mean-square value

29/0814	• • • {Field measurements related to measuring
	influence on or from apparatus, components
	or humans (EMC, EMI and similar testing
	in general G01R 31/001), e.g. in ESD, EMI,
	EMC, EMP testing, measuring radiation
	leakage; detecting presence of micro- or
	radiowave emitters; dosimetry; testing
	shielding; measurements related to lightning}
29/0821	• • • {rooms and test sites therefor, e.g. anechoic
	chambers, open field sites or TEM cells (for
	testing antennas G01R 29/105)}
29/0828	{TEM-cells}
29/0835	• • • {Testing shielding, e.g. for efficiency}
29/0842	• • • • {Measurements related to lightning, e.g.
	measuring electric disturbances, warning
	systems}
29/085	• • • { for detecting presence or location of electric
	lines or cables (fault detection G01R 31/50;
	fault location <u>G01R 31/08</u>)}
29/0857	{Dosimetry, i.e. measuring the time integral
	of radiation intensity; Level warning devices
	for personal safety use (nuclear radiation
	dosimetry <u>G01T</u>)}
29/0864	• • {characterised by constructional or functional
	features }
29/0871	{Complete apparatus or systems; circuits,
	e.g. receivers or amplifiers (<u>G01R 29/0878</u> ,
	<u>G01R 29/0892</u> take precedence; dosimeters,
20/0070	warning devices <u>G01R 29/0857</u>)}
29/0878	{Sensors; antennas; probes; detectors (wave
29/0885	guide measuring sections <u>G01R 1/24</u>)}
29/0885	{using optical probes, e.g. electro-optical,
	luminescent, glow discharge, or optical interferometers}
29/0892	• • {Details related to signal analysis or treatment;
29/0892	presenting results, e.g. displays; measuring
	specific signal features other than field
	strength, e.g. polarisation, field modes, phase,
	envelope, maximum value}
29/10	Radiation diagrams of antennas
29/105	• • {using anechoic chambers; Chambers or
29/103	open field sites used therefor (test sites used
	for measuring on other objects than aerials
	G01R 29/0828; wave absorbing devices
	H01Q 17/00)}
29/12	• Measuring electrostatic fields {or voltage-potential}
29/14	• • Measuring field distribution
29/16	• Measuring asymmetry of polyphase networks
29/18	• Indicating phase sequence; Indicating synchronism
29/20	 Measuring number of turns; Measuring
	transformation ratio or coupling factor of windings
29/22	• Measuring piezoelectric properties
29/24	• Arrangements for measuring quantities of charge
29/26	• Measuring noise figure; Measuring signal-to-noise
	ratio

	<u>G01R 33/1238;</u> } testing or measuring semiconductors
	or solid state devices during manufacture
	{ <u>H01L 22/00</u> }; testing line transmission systems H04B 3/46)
	<u>NOTE</u>
	Groups <u>G01R 31/08</u> , <u>G01R 31/12</u> , <u>G01R 31/327</u> , <u>G01R 31/24</u> , <u>G01R 31/26</u> , <u>G01R 31/34</u> , <u>G01R 31/36</u> , <u>G01R 31/40</u> , <u>G01R 31/44</u> take
	precedence over group $GO1R 31/50$.
31/001	• {Measuring interference from external sources to, or emission from, the device under test, e.g. EMC, EMI, EMP or ESD testing (measuring electromagnetic fields <u>G01R 29/08</u> ; circuits for generating HV pulses in dielectric strength testing <u>G01R 31/14</u>)}
31/002	• • {where the device under test is an electronic circuit}
31/003	• {Environmental or reliability tests (of individual
	semiconductors <u>G01R 31/2642;</u> of PCB's
	<u>G01R 31/2817;</u> of IC's <u>G01R 31/2855;</u> of other circuits <u>G01R 31/2849</u>)}
31/005	• {Testing of electric installations on transport
	means}
31/006	• • {on road vehicles, e.g. automobiles or trucks
	(testing of ignition installations peculiar to
21/007	internal combustion engines <u>F02P 17/00</u>)}
31/007 31/008	• • { using microprocessors or computers }
51/008	 {on air- or spacecraft, railway rolling stock or sea-going vessels}
31/01	• Subjecting similar articles in turn to test, e.g. "go/
	no-go" tests in mass production; Testing objects
	at points as they pass through a testing station
	(testing of cables continuously passing the testing apparatus <u>G01R 31/59</u> ; testing dielectric strength or
	breakdown voltage <u>G01R 31/12</u>)
31/013	• {Testing passive components (testing relays
	<u>G01R 31/3278;</u> testing electrical windings, e.g.
	inductors <u>G01R 31/72</u>)}
31/016	{Testing of capacitors (measuring capacitance <u>G01R 27/2605</u>)}
31/08	 Locating faults in cables, transmission lines, or networks
31/081	• • {according to type of conductors}
31/083	• • {in cables, e.g. underground}
31/085	• • • {in power transmission or distribution lines, e.g. overhead}
31/086	• • { in power transmission or distribution networks, i.e. with interconnected conductors }
31/088	• {Aspects of digital computing}
31/10	• • by increasing destruction at fault, e.g. burning- in by using a pulse generator operating a special
01/11	programme
31/11	• • using pulse reflection methods

Arrangements for testing electric properties; Arrangements for locating electric faults; Arrangements for electrical testing characterised

by what is being tested not provided for elsewhere ({measuring superconductive properties

31/00

31/12	• Testing dielectric strength or breakdown voltage {; Testing or monitoring effectiveness or level of insulation, e.g. of a cable or of an apparatus, for example using partial discharge measurements; Electrostatic testing (<u>G01R 31/08, G01R 31/327</u> and <u>G01R 31/72</u> take precedence; measuring in plasmas <u>G01R 19/0061</u> ; measuring dielectric constants <u>G01R 27/2617</u> ; ESD, EMC or EMP testing of circuits <u>G01R 31/002</u>)}
31/1209	 {using acoustic measurements (acoustic measurements <u>G01H 3/00</u>)}
31/1218	• • {using optical methods; using charged particle, e.g. electron, beams or X-rays}
31/1227	 {of components, parts or materials (G01R 31/1209, G01R 31/1218, G01R 31/18 take precedence; circuits therefor G01R 31/14; testing vessels of electrodes G01R 31/16)}
31/1236	• • {of surge arresters (monitoring overvoltage diverters or arresters <u>H02H 3/048</u>)}
31/1245	• • {of line insulators or spacers, e.g. ceramic overhead line cap insulators; of insulators in HV bushings}
31/1254	• • {of gas-insulated power appliances or vacuum gaps (testing switches <u>G01R 31/327</u> ; detecting electrical or mechanical defects in encased switchgear <u>H02B 13/065</u>)}
31/1263	• • {of solid or fluid materials, e.g. insulation films, bulk material; of semiconductors or LV electronic components or parts; of cable, line or wire insulation}
31/1272	• • • • {of cable, line or wire insulation, e.g. using partial discharge measurements (locating faults in cables <u>G01R 31/083</u>)}
31/1281	•••• {of liquids or gases}
31/129	• • • {of components or parts made of semiconducting materials; of LV components or parts (<u>G01R 31/18</u> takes precedence)}
31/14	 Circuits therefor {, e.g. for generating test voltages, sensing circuits (G01R 31/1209 - G01R 31/1227 take precedence; for testing switches G01R 31/327)}
31/16	• Construction of testing vessels; Electrodes therefor
31/18	• Subjecting similar articles in turn to test, e.g. go/ no-go tests in mass production
31/20	• Preparation of articles or specimens to facilitate testing
31/24	• Testing of discharge tubes (during manufacture <u>H01J 9/42</u>)
31/245	• • {Testing of gas discharge tubes}
31/25	• • Testing of vacuum tubes
31/252	• • {Testing of electron multipliers, e.g. photo- multipliers}
31/255	• • {Testing of transit-time tubes, e.g. klystrons, magnetrons}
31/257	• • {Testing of beam-tubes, e.g. cathode-ray tubes, image pick-up tubes (of channel image intensifier arrays <u>G01R 31/252</u> ; of transit time tubes <u>G01R 31/255</u>)}
31/26	 Testing of individual semiconductor devices (testing or measuring during manufacture or treatment {<u>H01L 22/00</u>}; testing of photovoltaic devices <u>H02S 50/10</u>)

31/2601	• {Apparatus or methods therefor (<u>G01R 31/2607</u> , <u>G01R 31/2642</u> take precedence)}
31/2603	• • {for curve tracing of semiconductor characteristics, e.g. on oscilloscope}
31/2607	• {Circuits therefor (G01R 31/2642 takes
	precedence)}
31/2608	• • { for testing bipolar transistors }
31/261	• • • • {for measuring break-down voltage or punch
	through voltage therefor}
31/2612	• • • { for measuring frequency response
	characteristics, e.g. cut-off frequency thereof}
31/2614	• • • { for measuring gain factor thereof }
31/2616	{for measuring noise (measuring noise factor in general <u>G01R 29/26</u>)}
31/2617	• • • { for measuring switching properties thereof }
31/2619	• • • • {for measuring thermal properties thereof}
31/2621	• • { for testing field effect transistors, i.e. FET's }
31/2623	
31/2625	• • • • {for measuring gain factor thereof}
31/2626	• • • {for measuring noise (measuring noise factor in general <u>G01R 29/26</u>)}
31/2628	• • • • {for measuring thermal properties thereof}
31/263	• • • {for testing thyristors}
31/2632	 {for testing diodes}
31/2633	• • • { for measuring switching properties thereof }
31/2635	•••• {Testing light-emitting diodes, laser diodes or photodiodes}
31/2637	 {for testing other individual devices (G01R 31/2608 - G01R 31/2632, G01R 31/27 take precedence)}
31/2639	• • • { for testing field-effect devices, e.g. of
51/2057	MOS-capacitors (<u>G01R 31/2621</u> takes
	precedence)}
21/2641	
31/2641	• • { for testing charge coupled devices }
31/2642	• • {Testing semiconductor operation lifetime or reliability, e.g. by accelerated life tests}
31/2644	• • {Adaptations of individual semiconductor devices to facilitate the testing thereof}
31/2646	• • { for measuring noise (<u>G01R 31/2616</u> ,
	<u>G01R 31/2626</u> take precedence)}
31/2648	• • {Characterising semiconductor materials
	(testing of materials or semi-finished products
	G01R 31/2831; testing during manufacture
	<u>H01L 22/00</u>)}
31/265	• Contactless testing {(of circuits, also in wafer-
	form <u>G01R 31/302</u>)}
31/2653	• • {using electron beams}
31/2656	• • • {using non-ionising electromagnetic radiation,
	e.g. optical radiation}
31/27	• • Testing of devices without physical removal
	from the circuit of which they form part, e.g.
	compensating for effects surrounding elements
	{(testing printed circuit boards <u>G01R 31/2801</u>)}
31/275	• • • { for testing individual semiconductor
	components within integrated circuits}
31/28	• Testing of electronic circuits, e.g. by signal tracer
	({EMC, EMP or similar testing of electronic
	circuits <u>G01R 31/002;</u> } testing for short-circuits,
	discontinuities, leakage or incorrect line connection
	<u>G01R 31/50;</u> checking computers {or computer
	components} <u>G06F 11/00;</u> checking static stores for
	correct operation $\underline{G11C} \underline{29/00}$ {; testing receivers or
	transmitters of transmission systems $H04B 17/00$ }
	(ansimilation of (ansimission systems n04D 1//00))

31/2801	 {Testing of printed circuits, backplanes, motherboards, hybrid circuits or carriers for multichip packages [MCP] (<u>G01R 31/318508</u>
	takes precedence; contactless testing <u>G01R 31/302</u> ; testing contacts or connections <u>G01R 31/66</u>)}
31/2803	• • • {by means of functional tests, e.g. logic-circuit- simulation or algorithms therefor (testing electronic digital computers <u>G06F 11/00</u>)}
31/2805	• • • {Bare printed circuit boards}
31/2806	• • • {Apparatus therefor, e.g. test stations,
	drivers, analysers, conveyors (<u>G01R 31/2805</u> , <u>G01R 31/281</u> , <u>G01R 31/2818</u> take precedence)}
31/2808	• • • {Holding, conveying or contacting
	devices, e.g. test adapters, edge connectors, extender boards (probe, multiprobe, probe manipulator or probe fixture <u>G01R 1/067</u>)}
31/281	• • • {Specific types of tests or tests for a specific
	type of fault, e.g. thermal mapping, shorts testing (G01R 31/2818 takes precedence)}
31/2812	• • • {Checking for open circuits or shorts,
	e.g. solder bridges; Testing conductivity,
	resistivity or impedance (of connections <u>G01R 31/66</u>)}
31/2813	• • • {Checking the presence, location, orientation
	or value, e.g. resistance, of components or
	conductors (orientation of the DUT with
	respect to the test fixture <u>G01R 1/06705</u> , G01R 31/281)}
31/2815	• • • {Functional tests, e.g. boundary scans, using
	the normal I/O contacts (contacting devices
	<u>G01R 31/2808;</u> testing digital circuits <u>G01R 31/317</u> , <u>G06F 11/00</u>)}
31/2817	• • • {Environmental-, stress-, or burn-in tests
01/2017	(of IC's <u>G01R 31/2855;</u> of individual
	semiconductors <u>G01R 31/2642</u> ; of other
	circuits <u>G01R 31/2849</u>)}
31/2818	• • • {using test structures on, or modifications
	of, the card under test, made for the purpose
	of testing, e.g. additional components or
	connectors (<u>G01R 31/2805</u> takes precedence;
	printed circuits having, e.g. symbols, test patterns or visualisation means <u>H05K 1/0266</u>)}
31/282	• {Testing of electronic circuits specially adapted
51/202	for particular applications not provided for
	elsewhere (<u>G01R 31/2801</u> and <u>G01R 31/2851</u>
	take precedence)}
	NOTE
	References listed below indicate CPC places which could also be of interest when carrying
	out a search in respect of the subject matter
	covered by the preceding group:
	• testing of individual LEDs <u>G01R 31/2635</u>
	• testing of lamps <u>G01R 31/44</u>
	 testing of displays and display drivers, e.g. LCDs <u>G09G 3/006</u>
	 testing of ADCs or DACs <u>H03M 1/1071</u>
31/2822	• • • {of microwave or radiofrequency circuits (of
	attenuation, gain, e.g. using network analyzers
	<u>G01R 27/28</u>)}
31/2824	{testing of oscillators or resonators}

- 31/2825 . . . {in household appliances or professional audio/ video equipment (testing LAN's <u>H04L 43/50</u>; testing TV systems <u>H04N 17/00</u>; testing loudspeakers <u>H04R 29/00</u>)}
- 31/2827 . . . {Testing of electronic protection circuits (testing switches <u>G01R 31/327</u>; checking alarm systems <u>G08B 29/00</u>; self test of summation current transformers <u>H02H 3/335</u>)}
- 31/2829 . . . {Testing of circuits in sensor or actuator systems (testing of apparatus for measuring electric or magnetic variables <u>G01R 35/00</u>; testing of indicating or recording apparatus <u>G01D</u>; in airbag systems <u>B60R 21/0173</u>; checking gas analysers <u>G01N 33/007</u>; monitoring or fail-safe circuits for electromagnets <u>H01F 7/1844</u>)}
- 31/2831 . . . {Testing of materials or semi-finished products, e.g. semiconductor wafers or substrates (G01R 31/318511 takes precedence; testing during manufacture H01L 22/00)}
- 31/2832 • {Specific tests of electronic circuits not provided for elsewhere (<u>G01R 31/2801, G01R 31/316</u> take precedence)}
- 31/2834 . . . {Automated test systems [ATE]; using microprocessors or computers (G01R 31/317 takes precedence; ATE for detection of defective computer hardware G06F 11/2736)}
- 31/2836 • {Fault-finding or characterising (G01R 31/2822 - G01R 31/2831 take precedence)}
- 31/2837 . . . {Characterising or performance testing, e.g. of frequency response (transient response GOIR 27/28)}
- 31/2839 . . . {using signal generators, power supplies or circuit analysers (<u>G01R 31/2879</u> takes precedence; multimeters <u>G01R 15/12</u>, network analysers <u>G01R 27/28</u>)}
- 31/2841.... {Signal generators}31/2843.... {In-circuit-testing}
- 31/2843 . . . {Inconcurrent lesting / 31/2844 . . . {using test interfaces, e.g. adapters, test boxes, switches, PIN drivers (G01R 31/2889 takes precedence)}
- 31/2846 . . . {using hard- or software simulation or using knowledge-based systems, e.g. expert systems, artificial intelligence or interactive algorithms}
- 31/2848 {using simulation}
 31/2849 . . . {Environmental or reliability testing, e.g. burn-in or validation tests (of individual semiconductors <u>G01R 31/2642</u>; of printed circuits boards <u>G01R 31/2817</u>; of IC's <u>G01R 31/2855</u>)}
- 31/2851 • {Testing of integrated circuits [IC] (<u>G01R 31/317</u> takes precedence; testing individual devices <u>G01R 31/26</u>; testing printed circuits <u>G01R 31/2801</u>)}
- $\begin{array}{cccc} 31/2853 & \ldots & \{ \mbox{Electrical testing of internal connections} & \\ & \mbox{or -isolation, e.g. latch-up or chip-to-lead} & \\ & \mbox{connections } (\underline{G01R \ 31/31717} \ takes \ precedence; & \\ & \mbox{test of chip-to-PCB or lead-to-PCB connections} & \\ & \mbox{G01R \ 31/66}) \} \end{array}$
- 31/2855 . . {Environmental, reliability or burn-in testing} 31/2856 . . . {Internal circuit aspects, e.g. built-in test
 - . . . {Internal circuit aspects, e.g. built-in test features; Test chips; Measuring material aspects, e.g. electro migration [EM]}

31/2858	
51/2050	•••• {Measuring of material aspects, e.g.
	electro-migration [EM], hot carrier
	injection }
31/286	• • • {External aspects, e.g. related to chambers,
21/20/20	contacting devices or handlers}
31/2862 31/2863	{Chambers or ovens; Tanks}
51/2805	•••• {Contacting devices, e.g. sockets, burn- in boards or mounting fixtures (in general
	$\underline{G01R 1/04}$
31/2865	• • • • {Holding devices, e.g. chucks; Handlers
01/2000	or transport devices (having contacts
	<u>G01R 31/2863</u>)}
31/2867	••••• {Handlers or transport devices, e.g.
	loaders, carriers, trays}
31/2868	•••• {Complete testing stations; systems;
	procedures; software aspects}
31/287	{Procedures; Software aspects}
31/2872	{related to electrical or environmental
	aspects, e.g. temperature, humidity,
21/2074	vibration, nuclear radiation}
31/2874 31/2875	{related to temperature}
31/2873	<pre> {related to heating} {related to cooling}</pre>
31/2877	• • • • {related to cooling}
51/2079	voltage or current supply or stimuli or to
	electrical loads}
31/2881	{related to environmental aspects other
	than temperature, e.g. humidity or
	vibrations}
31/2882	• • {Testing timing characteristics}
31/2884	• • • {using dedicated test connectors, test
	elements or test circuits on the IC under test
31/2886	(G01R 31/2855 takes precedence)}
51/2000	• • {Features relating to contacting the IC under test, e.g. probe heads; chucks (G01R 31/2865
	takes precedence, test connections, e.g. test sockets, or probes <u>per se, G01R 1/04</u> or
	takes precedence, test connections, e.g. test sockets, or probes <u>per se</u> , <u>G01R 1/04</u> or <u>G01R 1/06</u>)}
31/2887	 takes precedence, test connections, e.g. test sockets, or probes <u>per se, G01R 1/04</u> or <u>G01R 1/06</u>) {involving moving the probe head or the IC
31/2887	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>) {involving moving the probe head or the IC under test; docking stations (moving single
31/2887	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>) {involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/06705</u>; moving individual
	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>) {involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/06705;</u> moving individual probes in multiple probes <u>G01R 1/07392</u>)}
31/2887 31/2889	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>) . {involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/06705</u>; moving individual probes in multiple probes <u>G01R 1/07392</u>)} {Interfaces, e.g. between probe and tester
	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>)} . (involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/06705</u>; moving individual probes in multiple probes <u>G01R 1/07392</u>)} . {Interfaces, e.g. between probe and tester (<u>G01R 31/31905</u> and <u>G01R 1/07364</u> take
	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>)} . (involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/06705</u>; moving individual probes in multiple probes <u>G01R 1/07392</u>)} . {Interfaces, e.g. between probe and tester (<u>G01R 31/31905</u> and <u>G01R 1/07364</u> take precedence)} . {related to sensing or controlling of force,
31/2889	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>)} . (involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/06705</u>; moving individual probes in multiple probes <u>G01R 1/07392</u>)} . {Interfaces, e.g. between probe and tester (<u>G01R 31/31905</u> and <u>G01R 1/07364</u> take precedence)} . {related to sensing or controlling of force, position, temperature (<u>G01R 31/2874</u>
31/2889	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>) . (involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/06705</u>; moving individual probes in multiple probes <u>G01R 1/07392</u>) . {Interfaces, e.g. between probe and tester (<u>G01R 31/31905</u> and <u>G01R 1/07364</u> take precedence)} . {related to sensing or controlling of force, position, temperature (<u>G01R 31/2874</u> takes precedence; sensing of force <u>G01L</u>;
31/2889	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} . (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} . {Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} . {related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing
31/2889	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} . (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} . {Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} . {related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general
31/2889 31/2891	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} . (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} . {Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} . {related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)}
31/2889	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} . (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} . {Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} . {related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)} . {Handling, conveying or loading, e.g. belts,
31/2889 31/2891	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} . (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} . {Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} . {related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)}
31/2889 31/2891	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>) (involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/0705</u>; moving individual probes in multiple probes <u>G01R 1/07392</u>) {Interfaces, e.g. between probe and tester (<u>G01R 31/31905</u> and <u>G01R 1/07364</u> take precedence)} {related to sensing or controlling of force, position, temperature (<u>G01R 31/2874</u> takes precedence; sensing of force <u>G01L</u>; sensing of position <u>G01B</u>, <u>G01D</u>; sensing of temperature <u>G01K</u>; controlling in general <u>G05</u>)} {Handling, conveying or loading, e.g. belts, boats, vacuum fingers (<u>G01R 31/2867</u> takes precedence; handling semiconductor devices or wafers during manufacture or treatment
31/2889 31/2891 31/2893	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>) (involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/06705</u>; moving individual probes in multiple probes <u>G01R 1/07392</u>) {Interfaces, e.g. between probe and tester (<u>G01R 31/31905</u> and <u>G01R 1/07364</u> take precedence)} {related to sensing or controlling of force, position, temperature (<u>G01R 31/2874</u> takes precedence; sensing of force <u>G01L</u>; sensing of position <u>G01B</u>, <u>G01D</u>; sensing of temperature <u>G01K</u>; controlling in general <u>G05</u>)} {Handling, conveying or loading, e.g. belts, boats, vacuum fingers (<u>G01R 31/2867</u> takes precedence; handling semiconductor devices or wafers during manufacture or treatment <u>H01L 21/67</u>)}
31/2889 31/2891	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} (Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)) (related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)} (Handling, conveying or loading, e.g. belts, boats, vacuum fingers (G01R 31/2867 takes precedence; handling semiconductor devices or wafers during manufacture or treatment H01L 21/67)} (Aspects of quality control [QC]
31/2889 31/2891 31/2893	 takes precedence, test connections, e.g. test sockets, or probes <u>per se</u>, <u>G01R 1/04</u> or <u>G01R 1/06</u>) (involving moving the probe head or the IC under test; docking stations (moving single probes <u>G01R 1/06705</u>; moving individual probes in multiple probes <u>G01R 1/07392</u>) {Interfaces, e.g. between probe and tester (<u>G01R 31/31905</u> and <u>G01R 1/07364</u> take precedence)} {related to sensing or controlling of force, position, temperature (<u>G01R 31/2874</u> takes precedence; sensing of force <u>G01L</u>; sensing of position <u>G01B</u>, <u>G01D</u>; sensing of temperature <u>G01K</u>; controlling in general <u>G05</u>)} {Handling, conveying or loading, e.g. belts, boats, vacuum fingers (<u>G01R 31/2867</u> takes precedence; handling semiconductor devices or wafers during manufacture or treatment <u>H01L 21/67</u>)} {Aspects of quality control [QC] (<u>G01R 31/31718</u> takes precedence; program
31/2889 31/2891 31/2893 31/2894	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} (Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} (related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)} (Handling, conveying or loading, e.g. belts, boats, vacuum fingers (G01R 31/2867 takes precedence; handling semiconductor devices or wafers during manufacture or treatment H01L 21/67)} (Aspects of quality control [QC] (G01R 31/31718 takes precedence; program control for QC G05B 19/41875)}
31/2889 31/2891 31/2893	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} (Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} (related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)} (Handling, conveying or loading, e.g. belts, boats, vacuum fingers (G01R 31/2867 takes precedence; handling semiconductor devices or wafers during manufacture or treatment H01L 21/67)} (Aspects of quality control [QC] (G01R 31/31718 takes precedence; program control for QC G05B 19/41875)} (Testing of IC packages; Test features related
31/2889 31/2891 31/2893 31/2894	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} (Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} (related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)} (Handling, conveying or loading, e.g. belts, boats, vacuum fingers (G01R 31/2867 takes precedence; handling semiconductor devices or wafers during manufacture or treatment H01L 21/67)} (Aspects of quality control [QC] (G01R 31/31718 takes precedence; program control for QC G05B 19/41875)} (Testing of IC packages; Test features related to IC packages (containers per se H01L 23/02,
31/2889 31/2891 31/2893 31/2894	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} (Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} (related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)} (Handling, conveying or loading, e.g. belts, boats, vacuum fingers (G01R 31/2867 takes precedence; handling semiconductor devices or wafers during manufacture or treatment H01L 21/67)} (Aspects of quality control [QC] (G01R 31/31718 takes precedence; program control for QC G05B 19/41875)} (Testing of IC packages; Test features related to IC packages (containers per se H01L 23/02, encapsulations per se H01L 23/28)}
31/2889 31/2891 31/2893 31/2894 31/2896	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} (involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} (Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} (related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)} (Handling, conveying or loading, e.g. belts, boats, vacuum fingers (G01R 31/2867 takes precedence; handling semiconductor devices or wafers during manufacture or treatment H01L 21/67)} (Aspects of quality control [QC] (G01R 31/31718 takes precedence; program control for QC G05B 19/41875)} (Testing of IC packages; Test features related to IC packages (containers per se H01L 23/02, encapsulation, etg. removing encapsulation, etching (sample preparation in
31/2889 31/2891 31/2893 31/2894 31/2896	 takes precedence, test connections, e.g. test sockets, or probes per se, G01R 1/04 or G01R 1/06)} {involving moving the probe head or the IC under test; docking stations (moving single probes G01R 1/06705; moving individual probes in multiple probes G01R 1/07392)} {Interfaces, e.g. between probe and tester (G01R 31/31905 and G01R 1/07364 take precedence)} {related to sensing or controlling of force, position, temperature (G01R 31/2874 takes precedence; sensing of force G01L; sensing of position G01B, G01D; sensing of temperature G01K; controlling in general G05)} {Handling, conveying or loading, e.g. belts, boats, vacuum fingers (G01R 31/2867 takes precedence; handling semiconductor devices or wafers during manufacture or treatment H01L 21/67)} {Aspects of quality control [QC] (G01R 31/31718 takes precedence; program control for QC G05B 19/41875)} {Testing of IC packages; Test features related to IC packages (containers per se H01L 23/28)} {Sample preparation, e.g. removing

31/30	• • Marginal testing, e.g. by varying supply voltage
	(testing computers during standby operation or
	idle time <u>G06F 11/22</u>)
31/3004	• • • {Current or voltage test}
31/3008	{Quiescent current [IDDQ] test or leakage
21/2012	current test}
31/3012	{Built-In-Current test [BIC]}
31/3016	• • {Delay or race condition test, e.g. race hazard test}
31/302	 Contactless testing {(<u>G01R 31/66</u> takes precedence)}
31/3025	• • • {Wireless interface with the DUT}
31/3023	of integrated circuits
51/505	(<u>G01R 31/305</u> - <u>G01R 31/315</u> take precedence)
31/304	• • • of printed or hybrid circuits
	(G01R 31/305 - G01R 31/315 take precedence)
31/305	• • • using electron beams {(investigating or
	analysing materials by measuring photoelectric effect G01N 23/227)}
31/306	• • • • of printed or hybrid circuits
31/307	of integrated circuits
31/308	 using non-ionising electromagnetic radiation,
51/500	e.g. optical radiation {(investigating or
	analysing materials by the use of optical means
	<u>G01N 21/00;</u> image analysis <u>G06T 7/00</u>)}
31/309	• • • • of printed or hybrid circuits {or circuit
	substrates }
31/311	• • • of integrated circuits {(<u>G01R 31/31728</u> takes
	precedence)}
31/312	by capacitive methods
31/315	• • • by inductive methods
31/316	• Testing of analog circuits { $(G01R 31/2851 takes)$
21/2161	precedence)}
31/3161	• • Marginal testing
31/3163 31/3167	Functional testingTesting of combined analog and digital circuits
51/5107	{(testing ADC's <u>H03M 1/1071</u>)}
31/317	Testing of digital circuits
51/51/	
	WARNING
	The following subgroups of <u>G01R 31/317</u>
	are not complete due to an ongoing
	reorganisation : <u>G01R 31/31702</u> , <u>G01R 31/31708, G01R 31/31711</u> ,
	<u>G01R 31/31717, G01R 31/31718,</u>
	G01R 31/31728, G01R 31/31901. See also
	<u>G01R 31/317</u> and its other subgroups
31/31701	(Arrangements for setting the Unit Under Test
51/51/01	• • {Arrangements for setting the Unit Under Test [UUT] in a test mode}
31/31702	• • {Testing digital circuits including elements
51/51/02	other than semiconductor transistors, e.g.
	biochips, nanofabrics, mems, chips with
	magnetic elements }
31/31703	• • • {Comparison aspects, e.g. signature
	analysis, comparators (concerning scan
	tests <u>G01R 31/318566</u> ; concerning testers
21/21704	<u>G01R 31/3193</u>)}
31/31704	• • {Design for test; Design verification (concerning scan tests <u>G01R 31/318583;</u>
	(concerning scan tests <u>GOTR 31/318583;</u> computer-aided design <u>GO6F 30/00</u>)}
	computer and design <u>coor soloo</u>))

31/31705	• • •	{Debugging aspects, e.g. using test circuits for debugging, using dedicated debugging test
		circuits (generation of test sequences therefor
		G01R 31/31835, using scan test therefor
		<u>G01R 31/318544</u>)}
31/31706		{involving differential digital signals, e.g.
		testing differential signal circuits, using
		differential signals for testing}
31/31707	•••	{Test strategies (methods for generation of test
21/21709		sequences <u>G01R 31/318371</u>)}
31/31708	•••	{Analysis of signal quality (<u>G01R 31/31901</u> takes precedence; measuring frequencies
		or analysing frequency spectra <u>per se</u>
		<u>G01R 23/00;</u> measuring non-linear distortion
		per se <u>G01R 23/20</u>)}
31/31709		• { Jitter measurements; Jitter generators
		(measuring jitter, noise figure or signal-to-
		noise ratio per se G01R 29/26; analysis of
		tester signals G01R 31/31901)}
31/3171		• {BER [Bit Error Rate] test}
31/31711		• {Evaluation methods, e.g. shmoo plots}
31/31712	• • •	{Input or output aspects}
31/31713		• {Input or output interfaces for test,
		e.g. test pins, buffers (for scan test
		<u>G01R 31/318572</u>)}
31/31715	•••	• {Testing of input or output circuits; test
		of circuitry between the I/C pins and the functional core, e.g. testing of input or output
		driver, receiver, buffer}
31/31716		• {Testing of input or output with loop-back}
31/31717	•••	 (results of input of subput with 1869 suck) (Interconnect testing (by scan techniques see
51/51/1/	•••	<u>G01R 31/31855</u>)}
31/31718		
31/31718	•••	{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler
31/31718	•••	{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management
31/31718		{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test
31/31718		{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects
		{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects <u>G01R 31/2808, G01R 31/2851</u>)}
31/31718 31/31719		{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects <u>G01R 31/2808, G01R 31/2851</u>)} {Security aspects, e.g. preventing unauthorised
31/31719		{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects <u>G01R 31/2808, G01R 31/2851</u>)} {Security aspects, e.g. preventing unauthorised access during test}
	· · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin</pre>
31/31719	· · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing}</pre>
31/31719 31/3172	· · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin</pre>
31/31719 31/3172	· · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test</pre>
31/31719 31/3172	· · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects <u>G01R 31/2808, G01R 31/2851</u>)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test <u>G01R 31/318575</u>)} {Addressing or selecting of test units, e.g.</pre>
31/31719 31/3172 31/31721	· · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects <u>G01R 31/2808, G01R 31/2851</u>)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test <u>G01R 31/318575</u>)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units</pre>
31/31719 31/3172 31/31721 31/31722	· · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test G01R 31/318575)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test G01R 31/318558)}</pre>
31/31719 31/3172 31/31721	· · · · · · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects <u>G01R 31/2808, G01R 31/2851</u>)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test <u>G01R 31/318575</u>)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test <u>G01R 31/318558</u>)} {Hardware for routing the test signal within</pre>
31/31719 31/3172 31/31721 31/31722	· · · · · · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test G01R 31/318575)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test G01R 31/318558)} {Hardware for routing the test signal within the device under test to the circuits to be</pre>
31/31719 31/3172 31/31721 31/31722	· · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test G01R 31/318575)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test G01R 31/318558)} {Hardware for routing the test signal within the device under test to the circuits to be tested, e.g. multiplexer for multiple core</pre>
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31/31719 31/3172 31/31721 31/31722 31/31723	· · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test G01R 31/318575)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test G01R 31/318558)} {Hardware for routing the test signal within the device under test to the circuits to be tested, e.g. multiplexer for multiple core testing, accessing internal nodes (routing the test signal to or from the device under test</pre>
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31/31719 31/3172 31/31721 31/31722 31/31723 31/31723	· · · · · · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test G01R 31/318575)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test G01R 31/318558)} {Hardware for routing the test signal within the device under test to the circuits to be tested, e.g. multiplexer for multiple core testing, accessing internal nodes (routing the test signal to or from the device under test G01R 31/31926)} {Test controller, e.g. BIST state machine (for scan test G01R 31/318555)}</pre>
31/31719 31/3172 31/31721 31/31722 31/31723 31/31723	· · · · · · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test G01R 31/318575)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test G01R 31/318558)} {Hardware for routing the test signal within the device under test to the circuits to be tested, e.g. multiplexer for multiple core testing, accessing internal nodes (routing the test signal to or from the device under test G01R 31/31926)} {Test controller, e.g. BIST state machine (for scan test G01R 31/318555)} {Timing aspects, e.g. clock distribution, skew, propagation delay (for tester hardware G01R 31/31927)}</pre>
31/31719 31/3172 31/31721 31/31722 31/31723 31/31723	· · · · · · · · · · · · · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test G01R 31/318575)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test G01R 31/318558)} {Hardware for routing the test signal within the device under test to the circuits to be tested, e.g. multiplexer for multiple core testing, accessing internal nodes (routing the test signal to or from the device under test G01R 31/31926)} {Test controller, e.g. BIST state machine (for scan test G01R 31/318555)} {Timing aspects, e.g. clock distribution, skew, propagation delay (for tester hardware G01R 31/31927)} . {Synchronization, e.g. of test, clock or strobe</pre>
31/31719 31/3172 31/31721 31/31722 31/31723 31/31724 31/31724	· · · · · · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects <u>G01R 31/2808, G01R 31/2851</u>)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test <u>G01R 31/318575</u>)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test <u>G01R 31/318558</u>)} {Hardware for routing the test signal within the device under test to the circuits to be tested, e.g. multiplexer for multiple core testing, accessing internal nodes (routing the test signal to or from the device under test <u>G01R 31/31926</u>)} {Test controller, e.g. BIST state machine (for scan test <u>G01R 31/318555</u>)} {Timing aspects, e.g. clock distribution, skew, propagation delay (for tester hardware <u>G01R 31/31937</u>)} . {Synchronization, e.g. of test, clock or strobe signals; Signals in different clock domains;</pre>
31/31719 31/3172 31/31721 31/31722 31/31723 31/31724 31/31724	· · · · · · · · · · · ·	<pre>{Logistic aspects, e.g. binning, selection, sorting of devices under test, tester/handler interaction networks, Test management software, e.g. software for test statistics or test evaluation, yield analysis (mechanical aspects G01R 31/2808, G01R 31/2851)} {Security aspects, e.g. preventing unauthorised access during test} {Optimisation aspects, e.g. using functional pin as test pin, pin multiplexing} {Power aspects, e.g. power supplies for test circuits, power saving during test (for scan test G01R 31/318575)} {Addressing or selecting of test units, e.g. transmission protocols for selecting test units (for scan test G01R 31/318558)} {Hardware for routing the test signal within the device under test to the circuits to be tested, e.g. multiplexer for multiple core testing, accessing internal nodes (routing the test signal to or from the device under test G01R 31/31926)} {Test controller, e.g. BIST state machine (for scan test G01R 31/318555)} {Timing aspects, e.g. clock distribution, skew, propagation delay (for tester hardware G01R 31/31927)} . {Synchronization, e.g. of test, clock or strobe</pre>

 circuits for testing clocks (<u>G01R 31/31725</u> takes precedence; concerning scan test <u>G01R 31/318552</u>, for tester hardware <u>G01R 31/31922</u>) 31/31728 {Optical aspects, e.g. opto-electronics used for testing, optical signal transmission for testing electronic circuits, electro-optic components to be tested in combination with electronic circuits, measuring light emission of digital circuits (probes having electro-optic elements <u>G01R 1/071</u>; electro-optic sampling for oscilloscopes <u>G01R 13/347</u>; contactless testing of individual semiconductor devices by optical means <u>G01R 31/2656</u>) 31/3173 Marginal testing 31/3177 Testing of logic operation, e.g. by logic analysers 31/3181 Functional testing (<u>G01R 31/3177</u> takes precedence) 31/3181 {Test pattern generators} 31/3183 {Test pattern generators} 31/3183 {Computer-aided, e.g. automatic test program generator [ATPG], program translations, test program debugging} 31/318314 {Tools, e.g. program interfaces, test suite, test bench, simulation hardware, test compiler, test program languages (simulation software <u>G01R 31/318357</u>;
 31/31728 {Optical aspects, e.g. opto-electronics used for testing, optical signal transmission for testing electronic circuits, electro-optic components to be tested in combination with electronic circuits, measuring light emission of digital circuits (probes having electro-optic elements G01R 1/071; electro-optic sampling for oscilloscopes G01R 13/347; contactless testing of individual semiconductor devices by optical means G01R 31/2656)} 31/3173 Marginal testing 31/3177 . Testing of logic operation, e.g. by logic analysers 31/3181 Functional testing (G01R 31/3177 takes precedence) 31/3181 {Test pattern generators} 31/3183 {Test pattern generators} 31/3183 {Computer testing; Soft error rate evaluation; Single event testing} 31/3183 {computer-aided, e.g. automatic test program generator [ATPG], program translations, test program debugging} 31/318314 {Tools, e.g. program interfaces, test suite, test bench, simulation hardware, test compiler, test program languages
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G01R 1/071; electro-optic sampling for oscilloscopes G01R 13/347; contactless testing of individual semiconductor devices by optical means G01R 31/2656)}31/3173.31/3173.Testing of logic operation, e.g. by logic analysers31/3181.Functional testing (G01R 31/3177 takes precedence)31/3181.Single event testing;31/3183.Generation of test inputs, e.g. test vectors, patterns or sequences31/31837.Single event festing;31/31831.Single event fest inputs, e.g. test vectors, patterns or sequences31/318314.Single event fest program debugging;31/318314.Single event fest program interfaces, test suite, test bench, simulation hardware, test compiler, test program languages
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suite, test bench, simulation hardware, test compiler, test program languages
α mulators COEE 11/261)
emulators <u>G06F 11/261</u>)} 31/318321 {for combinational circuits}
31/318328 {for delay tests}
31/318335 {Test pattern compression or
decompression (compression or
decompression of scan patterns
<u>G01R 31/318547;</u> compression
or decompression hardware G01R 31/31921)}
31/318342 • • • • {by preliminary fault modelling, e.g.
31/31835 {Analysis of test coverage or failure
detectability}
31/318357 {Simulation (computer simulation of digital circuits <u>G06F 30/3308</u>)}
31/318364 {as a result of hardware simulation, e.g. in an HDL environment (computer-aided
simulation of circuits <u>G06F 30/3308</u>)} 31/318371 {Methodologies therefor, e.g. algorithms,
procedures }
31/318378 {of patterns for devices arranged in a network}
31/318385 {Random or pseudo-random test pattern}
31/318392 {for sequential circuits (<u>G01R 31/318544</u> takes precedence)}
31/3185 Reconfiguring for testing, e.g. LSSD,
partitioning

31/318508 {Board Level Test, e.g. P1500 Standard (features related to boundary scan <u>GOLR 31/318533</u>)}
31/318511 • • • • • {Wafer Test}
31/318513 {Test of Multi-Chip-Moduls}
31/318516 {Test of programmable logic devices [PLDs]}
31/318519 { Test of field programmable gate arrays [FPGA]}
31/318522 {Test of Sequential circuits (test of
microprocessors <u>G06F 11/2236</u> , test of ALU's <u>G06F 11/2226</u>)}
31/318525 {Test of flip-flops or latches}
31/318527 {Test of counters}
31/31853 {Test of registers}
31/318533 • • • • {using scanning techniques, e.g. LSSD,
Boundary Scan, JTAG}
31/318536 {Scan chain arrangements, e.g. connections, test bus, analog signals}
31/318538 {Topological or mechanical aspects}
31/318541 {Scan latches or cell details}
31/318544 {Scanning methods, algorithms
and patterns (<u>G01R 31/3183</u> takes precedence)}
31/318547 {Data generators or compressors}
31/31855 {Interconnection testing, e.g.
crosstalk, shortcircuits }
31/318552 {Clock circuits details}
31/318555 {Control logic}
31/318558 {Addressing or selecting of subparts of
the device under test}
31/318563 {Multiple simultaneous testing of subparts}
31/318566 {Comparators; Diagnosing the device under test}
31/318569 • • • • • {Error indication, logging circuits}
31/318572 {Input/Output interfaces}
31/318575 {Power distribution; Power saving}
31/318577 {AC testing, e.g. current testing, burn-
in}
31/31858 {Delay testing}
31/318583 {Design for test}
31/318586 {with partial scan or non-scannable parts}
31/318588 {Security aspects}
31/318591 • • • • • • {Tools}
31/318594 {Timing aspects (clock circuits G01R 31/318552)}
31/318597 {JTAG or boundary scan test of memory
devices (other scan testing of memories G11C 29/32)
31/3187 Built-in tests
31/319 Tester hardware, i.e. output processing
circuits
31/31901 {Analysis of tester Performance; Tester
characterization}
31/31903 {tester configuration}
31/31905 { Interface with the device under test [DUT], e.g. arrangements between the test head and the DUT, mechanical
aspects, fixture}

31/31907	••••• {Modular tester, e.g. controlling and
	coordinating instruments in a bus based
	architecture }
31/31908	••••• {Tester set-up, e.g. configuring the
	tester to the device under test [DUT],
	down loading test patterns}
31/3191	{Calibration}
31/31912	• • • • • {Tester/user interface}
31/31914	• • • • • {Portable Testers}
31/31915	{In-circuit Testers}
31/31917	••••• {Stimuli generation or application of test
	patterns to the device under test [DUT]}
31/31919	••••• {Storing and outputting test patterns
	(G01R 31/31924 takes precedence;
	arithmetic and random test patterns
	generator)}
31/31921	••••• {using compression techniques, e.g.
	patterns sequencer}
31/31922	• • • • • {Timing generation or clock distribution
	(G01R 31/3191 takes precedence)}
31/31924	••••• {Voltage or current aspects, e.g. driver,
	receiver}
31/31926	{Routing signals to or from the device
	under test [DUT], e.g. switch matrix, pin multiplexing}
21/21029	1 0,
31/31928	{Formatter (driver, receiver details G01R 31/31924)}
31/3193	• • • • • with comparison between actual response
51/51/5	and known fault free response {(receiver
	details <u>G01R 31/31924</u>)}
31/31932	· · · · · {Comparators}
31/31935	••••• {Storing data, e.g. failure memory}
31/31937	••••• {Timing aspects, e.g. measuring
	propagation delay (G01R 31/3191
	and G01R 31/31922 take precedence;
	marginal testing G06F 11/24)}
31/327	• Testing of circuit interrupters, switches or circuit-
21/2271	breakers
31/3271	• • {of high voltage or medium voltage devices
31/3272	 (G01R 31/333 takes precedence)} . {Apparatus, systems or circuits therefor
51/5272	(<u>G01R 31/3275</u> takes precedence)}
31/3274	• • • {Details related to measuring, e.g. sensing,
51/52/4	displaying or computing; Measuring of
	variables related to the contact pieces, e.g.
	wear, position or resistance (measuring
	contact resistance <u>G01R 27/205</u>)
31/3275	• • • {Fault detection or status indication}
31/3277	• • {of low voltage devices, e.g. domestic or
	industrial devices, such as motor protections,
	relays, rotation switches}
31/3278	• • { of relays, solenoids or reed switches
	(measuring contact resistance <u>G01R 27/205;</u>
	high voltage magnetic switches <u>G01R 31/3271</u> , G01R 31/323: tasting electric windings
	<u>G01R 31/333;</u> testing electric windings <u>G01R 31/72;</u> monitoring of fail safe circuits
	$\underline{H01H}$ 47/002)
31/333	• Testing of the switching capacity of high-voltage
511555	circuit-breakers {; Testing of breaking capacity of
	related variables, e.g. post arc current or transient
	recovery voltage}
31/3333	{Apparatus, systems or circuits therefor}

31/3336	• • • {Synthetic testing, i.e. with separate current
	and voltage generators simulating distance
24/24	fault conditions}
31/34	• Testing dynamo-electric machines
31/343	• • {in operation}
31/346	• • {Testing of armature or field windings}
31/36	• Arrangements for testing, measuring or monitoring
	the electrical condition of accumulators or electric
	batteries, e.g. capacity or state of charge [SoC]
	NOTE
	{This group covers arrangements for measuring,
	testing or indicating electrical conditions or
	variables of accumulators or electric batteries.
	Arrangements for monitoring, measuring, testing
	or indicating condition structurally associated
	with the battery are covered by <u>H01M</u> , e.g. by
	group <u>H01M 10/48</u> }
31/364	Battery terminal connectors with integrated
	measuring arrangements
31/3644	• • {Constructional arrangements}
31/3646	• • • {for indicating electrical conditions or
	variables, e.g. visual or audible indicators}
31/3647	• • • { for determining the ability of a battery to
21/2640	perform a critical function, e.g. cranking}
31/3648	 • {comprising digital calculation means, e.g. for performing an algorithm}
31/367	• • Software therefor, e.g. for battery testing using
51/507	modelling or look-up tables
31/371	• with remote indication, e.g. on external chargers
31/374	• • with means for correcting the measurement for
	temperature or ageing
31/378	specially adapted for the type of battery or
	accumulator
31/379	for lead-acid batteries
31/38	• • {Primary cells, i.e. not rechargeable}
31/382	Arrangements for monitoring battery or accumulator variables, e.g. SoC
31/3828	using current integration
31/3832	••••••••••••••••••••••••••••••••••••••
31/3833	• • • • {using analog integrators, e.g. coulomb-
	meters}
31/3835	involving only voltage measurements
31/3842	combining voltage and current measurements
31/385	• Arrangements for measuring battery or
	accumulator variables (for monitoring
31/386	$\frac{G01R 31/382}{(using test loads)}$
31/3865	 • {using test-loads} • {related to manufacture, e.g. testing after
51/5005	manufacture}
31/387	Determining ampere-hour charge capacity or
	SoC
31/388	involving voltage measurements
31/389	Measuring internal impedance, internal
	conductance or related variables
31/392	• Determining battery ageing or deterioration, e.g.
01/00 -	state of health
31/396	. Acquisition or processing of data for testing or
	for monitoring individual cells or groups of cells within a battery
31/40	Testing power supplies (testing photovoltaic devices
51/40	H02S 50/10)
31/42	• • AC power supplies

31/44	• Testing lamps
31/44	 Testing famps Testing of electric apparatus, lines, cables or
51/50	components for short-circuits, continuity, leakage
	current or incorrect line connections (testing of
	sparking plugs H01T 13/58)
31/52	• Testing for short-circuits, leakage current or
51/52	ground faults
31/54	• • Testing for continuity
31/55	Testing for incorrect line connections
31/56	Testing of electric apparatus (testing of
51/50	transformers <u>G01R 31/62</u> ; testing of connections
	G01R 31/66)
31/58	• Testing of lines, cables or conductors (testing of
01,00	electric windings $G01R 31/72$)
31/59	• • • while the cable continuously passes the testing
	apparatus, e.g. during manufacture
31/60	Identification of wires in a multicore cable
31/62	• • Testing of transformers
31/64	• • Testing of capacitors
31/66	 Testing of connections, e.g. of plugs or non-
51/00	disconnectable joints (testing for incorrect line
	connections G01R 31/55)
31/67	Testing the correctness of wire connections in
	electric apparatus or circuits
31/68	• • Testing of releasable connections, e.g. of
	terminals mounted on a printed circuit board
31/69	of terminals at the end of a cable or a wire
	harness; of plugs; of sockets, e.g. wall
	sockets or power sockets in appliances
31/70	Testing of connections between components
	and printed circuit boards (G01R 31/68 takes
	precedence)
31/71	Testing of solder joints
31/71 31/72	Testing of electric windings (testing of
31/72	• Testing of electric windings (testing of transformers <u>G01R 31/62</u>)
	Testing of electric windings (testing of
31/72	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses
31/72 31/74	• Testing of electric windings (testing of transformers <u>G01R 31/62</u>)
31/72 31/74	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables
31/72 31/74 33/00	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring
31/72 31/74 33/00	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor
31/72 31/74 33/00	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic
31/72 31/74 33/00 33/0005	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic
31/72 31/74 33/00 33/0005	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor}
31/72 31/74 33/00 33/0005	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields
31/72 31/74 33/00 33/0005 33/0011	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for
31/72 31/74 33/00 33/0005 33/0011 33/0017	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields}
31/72 31/74 33/00 33/0005 33/0011	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation,
31/72 31/74 33/00 33/0005 33/0011 33/0017	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals;
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)}
31/72 31/74 33/00 33/0005 33/0011 33/0017	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise}
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g.
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029 33/0035	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g. integrated calibration}
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029 33/0035 33/0041	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g. integrated calibration} {using feed-back or modulation techniques}
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029 33/0035	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g. integrated calibration} {using feed-back or modulation techniques} {Housings or packaging of magnetic sensors
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029 33/0035 33/0041	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g. integrated calibration} {using feed-back or modulation techniques} {Housings or packaging of magnetic sensors (packaging of semiconductor devices <u>H01L 23/00</u>);
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029 33/0035 33/0041 33/0047	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g. integrated calibration} {using feed-back or modulation techniques} {Housings or packaging of magnetic sensors (packaging of semiconductor devices <u>H01L 23/00</u>); Holders}
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029 33/0035 33/0041	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g. integrated calibration} {using feed-back or modulation techniques} {Housings or packaging of magnetic sensors (packaging of semiconductor devices <u>H01L 23/00</u>); Holders} {Manufacturing aspects; Manufacturing of single
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029 33/0035 33/0041 33/0047	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g. integrated calibration} {using feed-back or modulation techniques} {Housings or packaging of magnetic sensors (packaging of semiconductor devices <u>H01L 23/00</u>); Holders} {Manufacturing aspects; Manufacturing of single devices, i.e. of semiconductor magnetic sensor chips
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029 33/0035 33/0041 33/0047	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g. integrated calibration} {using feed-back or modulation techniques} {Housings or packaging of magnetic sensors (packaging of semiconductor devices <u>H01L 23/00</u>); Holders} {Manufacturing aspects; Manufacturing of single devices, i.e. of semiconductor magnetic effect or the
31/72 31/74 33/00 33/0005 33/0011 33/0017 33/0023 33/0029 33/0035 33/0041 33/0047	 Testing of electric windings (testing of transformers <u>G01R 31/62</u>) Testing of fuses Arrangements or instruments for measuring magnetic variables {Geometrical arrangement of magnetic sensor elements; Apparatus combining different magnetic sensor types (<u>G01R 33/0206</u> takes precedence)} {comprising means, e.g. flux concentrators, flux guides, for guiding or concentrating the magnetic flux, e.g. to the magnetic sensor} {Means for compensating offset magnetic fields or the magnetic flux to be measured; Means for generating calibration magnetic fields} {Electronic aspects, e.g. circuits for stimulation, evaluation, control; Treating the measured signals; calibration (<u>G01R 33/0017</u> takes precedence)} {Treating the measured signals, e.g. removing offset or noise} {Calibration of single magnetic sensors, e.g. integrated calibration} {using feed-back or modulation techniques} {Housings or packaging of magnetic sensors (packaging of semiconductor devices <u>H01L 23/00</u>); Holders} {Manufacturing aspects; Manufacturing of single devices, i.e. of semiconductor magnetic sensor chips

33/0064	 {comprising means for performing simulations, e.g. of the magnetic variable to be measured}
33/007	• {Environmental aspects, e.g. temperature variations,
	radiation, stray fields (G01R 33/025 takes
	precedence)}
33/0076	• • {Protection, e.g. with housings against stray
22/0002	fields}
33/0082	{Compensation, e.g. compensating for temperature changes}
33/0088	• {use of bistable or switching devices, e.g. Reed-
22,0000	switches}
33/0094	• {Sensor arrays}
33/02	• Measuring direction or magnitude of magnetic
	fields or magnetic flux (<u>G01R 33/20</u> takes
	precedence)
	<u>NOTE</u>
	Groups G01R 33/022, G01R 33/10
	take precedence over groups
	<u>G01R 33/025</u> - <u>G01R 33/09</u> .
33/0206	• • {Three-component magnetometers}
33/0213	• • {using deviation of charged particles by the
	magnetic field}
33/022	Measuring gradient
33/025	• Compensating stray fields {(<u>G01R 33/0017</u> takes
33/028	precedence)}Electrodynamic magnetometers
33/028	 fin which a current or voltage is generated
55/0205	due to relative movement of conductor and
	magnetic field}
33/0286	• • • {comprising microelectromechanical systems
	[MEMS] (MEMS devices in general <u>B81B</u>)}
33/032	• using magneto-optic devices, e.g. Faraday {or
33/0322	Cotton-Mouton effect} {using the Faraday or Voigt effect}
33/0325	 {using the Faraday or Voigt effect} {using the Kerr effect}
33/0327	• • {with application of magnetostriction}
33/035	• using superconductive devices
33/0352	{Superconductive magneto-resistances}
33/0354	••• {SQUIDS}
33/0356	• • • • {with flux feedback}
33/0358	{coupling the flux to the SQUID
	(gradiometer coils <u>G01R 33/022</u> ; coils with superconductive winding <u>H01F 6/06</u>)}
33/038	• using permanent magnets, e.g. balances, torsion
55/050	devices
33/0385	{in relation with magnetic force measurements
	(magnetic force microscopes <u>G01Q 60/50</u>)}
33/04	using the flux-gate principle
33/045	• • {in single-, or multi-aperture elements}
33/05	• • • in thin-film element
33/06 33/063	• using galvano-magnetic devices
55/005	 {Magneto-impedance sensors; Nanocristallin sensors}
33/066	• • • {field-effect magnetic sensors, e.g. magnetic
-	transistor}
33/07	• • • Hall effect devices
33/072	{Constructional adaptation of the sensor to
22/075	specific applications}
33/075	• • • • {Hall devices configured for spinning current measurements}
33/077	• • • {Vertical Hall-effect devices}
33/09	Magnetoresistive devices

33/091	•••• {Constructional adaptation of the sensor to specific applications}
33/093	{using multilayer structures, e.g. giant magnetoresistance sensors (thin magnetic
	films <u>H01F 10/00</u>)}
33/095	• • • • {extraordinary magnetoresistance sensors}
33/096	• • • • {anisotropic magnetoresistance sensors}
33/098	• • • {comprising tunnel junctions, e.g. tunnel magnetoresistance sensors}
33/10	 Plotting field distribution {; Measuring field distribution}
33/12	• Measuring magnetic properties of articles or
	specimens of solids or fluids (involving magnetic resonance <u>G01R 33/20</u>)
33/1207	• {Testing individual magnetic storage devices,
55/1207	e.g. records carriers or digital storage elements (functional testing <u>G06F 11/00</u> , <u>G06F 11/28</u>)}
33/1215	• {Measuring magnetisation; Particular
55/1215	magnetometers therefor ($G01R 33/14$ takes
	precedence; electrodynamic magnetometers
	G01R 33/028)
33/1223	• {Measuring permeability, i.e. permeameters (G01R 33/14 takes precedence)}
33/123	• {Measuring loss due to hysteresis (<u>G01R 33/14</u>
	takes precedence)}
33/1238	• • {Measuring superconductive properties}
33/1246	• • • {Measuring critical current}
33/1253	• • {Measuring galvano-magnetic properties}
33/1261	• • {using levitation techniques}
33/1269	• • {of molecules labeled with magnetic
	beads (magnetic particles for bio assay G01N 33/54326)}
33/1276	• • {of magnetic particles, e.g. imaging of magnetic nanoparticles (<u>G01R 33/1269</u> takes precedence)}
33/1284	• {Spin resolved measurements; Influencing
	spins during measurements, e.g. in spintronics
	devices (G01R 33/093 takes precedence;
	semiconductor devices using spin polarized
	carriers H01L 29/66984)
33/1292	• • {Measuring domain wall position or domain wall
	motion}
33/14	• • Measuring or plotting hysteresis curves
	{(<u>G01R 33/1207</u> takes precedence)}
33/16	• Measuring susceptibility {(<u>G01R 33/1238</u> takes
	precedence)}
33/18	Measuring magnetostrictive properties
33/20	• involving magnetic resonance (medical aspects
	<u>A61B 5/055;</u> magnetic resonance gyrometers
	<u>G01C 19/60</u>)
33/24	• for measuring direction or magnitude of magnetic fields or magnetic flux
33/243	• • • {Spatial mapping of the polarizing magnetic
00/210	field}
33/246	• • {Spatial mapping of the RF magnetic field B1}
33/26	• • • using optical pumping
33/28	 Details of apparatus provided for in groups
	<u>G01R 33/44</u> - <u>G01R 33/64</u>
33/281	{Means for the use of <u>in vitro</u> contrast agents (<u>G01R 33/282</u> takes precedence; involving
	use of a contrast agent in MR imaging
	<u>G01R 33/5601; in vivo</u> contrast agents
	A61K 49/0002)}
	<u> </u>

33/282	• • • {Means specially adapted for hyperpolarisation
	or for hyperpolarised contrast agents, e.g. for the generation of hyperpolarised gases
	using optical pumping cells, for storing
	hyperpolarised contrast agents or for the
	determination of the polarisation of a
22/202	hyperpolarised contrast agent}. Intercom or optical viewing arrangements,
33/283	structurally associated with NMR apparatus}
33/285	• • • {Invasive instruments, e.g. catheters or biopsy
	needles, specially adapted for tracking, guiding or visualization by NMR }
33/286	• • • • {involving passive visualization of
33/200	interventional instruments, i.e. making the
	instrument visible as part of the normal MR
	process}
33/287	• • • • {involving active visualization of
	interventional instruments, e.g. using active tracking RF coils or coils for intentionally
	creating magnetic field inhomogeneities}
33/288	• • • {Provisions within MR facilities for enhancing
	safety during MR, e.g. reduction of the
	specific absorption rate [SAR], detection of
	ferromagnetic objects in the scanner room}
33/30	• • Sample handling arrangements, e.g. sample
33/302	cells, spinning mechanisms {Miniaturized sample handling arrangements
33/302	for sampling small quantities, e.g. flow-
	through microfluidic NMR chips}
33/305	{specially adapted for high-pressure
	applications}
33/307	• • • • {specially adapted for moving the
	sample relative to the MR system, e.g. spinning mechanisms, flow cells or
	means for positioning the sample inside a
	spectrometer}
33/31	Temperature control thereof
33/32	Excitation or detection systems, e.g. using radio
22/222	frequency signals
33/323	• • • {Detection of MR without the use of RF or microwaves, e.g. force-detected MR,
	thermally detected MR, MR detection via
	electrical conductivity, optically detected
	MR}
33/326	•••• {involving a SQUID}
33/34	Constructional details, e.g. resonators {,
33/34007	specially adapted to MR }
33/34007	printed circuit board technology;
	additional hardware for providing
	additional hardware for providing mechanical support to the RF coil
	additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support
	additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to
33/34015	additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to the remainder of the MR system}
33/34015 33/34023	additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to
	additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to the remainder of the MR system}
33/34023	 additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to the remainder of the MR system} {Temperature-controlled RF coils} {Superconducting RF coils} {Means for cooling of the RF coils, e.g. a refrigerator or a cooling vessel
33/34023	 additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to the remainder of the MR system} {Temperature-controlled RF coils} {Superconducting RF coils} {Means for cooling of the RF coils, e.g. a refrigerator or a cooling vessel specially adapted for housing an RF
33/34023 33/3403	 additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to the remainder of the MR system} {Temperature-controlled RF coils} {Superconducting RF coils} {Means for cooling of the RF coils, e.g. a refrigerator or a cooling vessel specially adapted for housing an RF coil}
33/34023 33/3403 33/34038	 additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to the remainder of the MR system} {Temperature-controlled RF coils} {Superconducting RF coils} {Means for cooling of the RF coils, e.g. a refrigerator or a cooling vessel specially adapted for housing an RF coil} {Loopless coils, i.e. linear wire antennas}
33/34023 33/3403	 additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to the remainder of the MR system} {Temperature-controlled RF coils} {Superconducting RF coils} {Means for cooling of the RF coils, e.g. a refrigerator or a cooling vessel specially adapted for housing an RF coil}
33/34023 33/3403 33/34038	 additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to the remainder of the MR system} {Temperature-controlled RF coils} {Superconducting RF coils} {Means for cooling of the RF coils, e.g. a refrigerator or a cooling vessel specially adapted for housing an RF coil} {Loopless coils, i.e. linear wire antennas} {Volume type coils, e.g. bird-cage coils; Quadrature bird-cage coils; Circularly polarised coils}
33/34023 33/3403 33/34038	 additional hardware for providing mechanical support to the RF coil assembly or to part thereof, e.g. a support for moving the coil assembly relative to the remainder of the MR system} {Temperature-controlled RF coils} {Superconducting RF coils} {Means for cooling of the RF coils, e.g. a refrigerator or a cooling vessel specially adapted for housing an RF coil} {Loopless coils, i.e. linear wire antennas} {Volume type coils, e.g. bird-cage coils; Quadrature bird-cage coils; Circularly

33/34061	••••• {Helmholtz coils}
33/34069	•••• {Saddle coils}
33/34076	• • • • • {Birdcage coils}
33/34084	•••• {implantable coils or coils being
	geometrically adaptable to the sample, e.g.
	flexible coils or coils comprising mutually
	movable parts}
33/34092	••••• {RF coils specially adapted for NMR
	spectrometers }
33/341	• • • • comprising surface coils
33/3415	••••• comprising arrays of sub-coils {, i.e.
	phased-array coils with flexible receiver
	channels}
33/343	• • • • of slotted-tube or loop-gap type
33/345	• • • • of waveguide type (<u>G01R 33/343</u> takes
	precedence)
33/3453	••••• (Transverse electromagnetic [TEM]
	coils}
33/3456	•••••• {Stripline resonators}
33/36	• • • Electrical details, e.g. matching or coupling
	of the coil to the receiver
33/3607	••••• {RF waveform generators, e.g. frequency
	generators, amplitude-, frequency- or
	phase modulators or shifters, pulse
	programmers, digital to analog converters
	for the RF signal, means for filtering or
	attenuating of the RF signal}
33/3614	• • • • {RF power amplifiers}
33/3621	• • • • • {NMR receivers or demodulators, e.g.
	preamplifiers, means for frequency
	modulation of the MR signal using a
	digital down converter, means for analog
	to digital conversion [ADC] or for filtering
	or processing of the MR signal such as
	bandpass filtering, resampling, decimation or interpolation }
33/3628	- · · ·
33/3028	{Tuning/matching of the transmit/receive coil}
33/3635	• • • • • {Multi-frequency operation}
33/3642	{Mutual coupling or decoupling of
55/3042	multiple coils, e.g. decoupling of a receive
	coil from a transmission coil, or intentional
	coupling of RF coils, e.g. for RF magnetic
	field amplification }
33/365	••••• {Decoupling of multiple RF coils
	wherein the multiple RF coils have the
	same function in MR, e.g. decoupling
	of a receive coil from another receive
	coil in a receive coil array, decoupling
	of a transmission coil from another
	transmission coil in a transmission coil
22/2/17	array}
33/3657	{Decoupling of multiple RF coils
	wherein the multiple RF coils do not
	have the same function in MR, e.g.
	decoupling of a transmission coil from a receive coil}

33/3664	•••• {Switching for purposes other than coil
	coupling or decoupling, e.g. switching
	between a phased array mode and a
	quadrature mode, switching between
	surface coil modes of different geometrical
	shapes, switching from a whole body
	reception coil to a local reception coil
	or switching for automatic coil selection
	in moving table MR or for changing
	the field-of-view (G01R 33/3671 takes
	precedence)}
33/3671	•••• {involving modulation of the quality
	factor of the RF coil (G01R 33/3642 takes
	precedence)}
33/3678	•••• {involving quadrature drive or detection,
	e.g. a circularly polarized RF magnetic
	field}
33/3685	•••• {Means for reducing sheath currents, e.g.
	RF traps, baluns}
33/3692	•••• {involving signal transmission without
	using electrically conductive connections,
	e.g. wireless communication or optical
	communication of the MR signal or an
	auxiliary signal other than the MR signal}
33/38	Systems for generation, homogenisation or
	stabilisation of the main or gradient magnetic
	field
33/3802	• • • • {Manufacture or installation of magnet
	assemblies; Additional hardware for
	transportation or installation of the magnet
	assembly or for providing mechanical
	support to components of the magnet
	assembly}
33/3804	• • • • {Additional hardware for cooling or heating
	of the magnet assembly, for housing a cooled
	or heated part of the magnet assembly or for
	temperature control of the magnet assembly}
33/3806	{Open magnet assemblies for improved
	access to the sample, e.g. C-type or U-type
	magnets}
33/3808	• • • • {Magnet assemblies for single-sided MR
22,2000	wherein the magnet assembly is located
	on one side of a subject only; Magnet
	assemblies for inside-out MR, e.g. for MR
	in a borehole or in a blood vessel, or magnet
	assemblies for fringe-field MR}
33/381	using electromagnets
33/3815	••••••••••••••••••••••••••••••••••••••
55,5015	
33/383	supply therefor
	supply therefor
	• • • • using permanent magnets
33/385	 using permanent magnets using gradient magnetic field coils
	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for
33/385	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient
33/385	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a
33/385 33/3852	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer}
33/385	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer} {means for active and/or passive vibration
33/385 33/3852	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer} {means for active and/or passive vibration damping or acoustical noise suppression in
33/385 33/3852 33/3854	 using permanent magnets using gradient magnetic field coils {Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer} {means for active and/or passive vibration damping or acoustical noise suppression in gradient magnet coil systems}
33/385 33/3852	 using permanent magnets using gradient magnetic field coils {Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer} {means for active and/or passive vibration damping or acoustical noise suppression in gradient magnet coil systems} {Means for cooling the gradient coils or
33/385 33/3852 33/3854 33/3856	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer} {means for active and/or passive vibration damping or acoustical noise suppression in gradient magnet coil systems} {Means for cooling the gradient coils or thermal shielding of the gradient coils}
33/385 33/3852 33/3854	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer} {means for active and/or passive vibration damping or acoustical noise suppression in gradient magnet coil systems} {Means for cooling the gradient coils or thermal shielding of the gradient coils} {Manufacture and installation of gradient
33/385 33/3852 33/3854 33/3856	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer} {means for active and/or passive vibration damping or acoustical noise suppression in gradient magnet coil systems} {Means for cooling the gradient coils or thermal shielding of the gradient coils} {Manufacture and installation of gradient coils, means for providing mechanical
33/385 33/3852 33/3854 33/3856	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer} {means for active and/or passive vibration damping or acoustical noise suppression in gradient magnet coil systems} {Means for cooling the gradient coils or thermal shielding of the gradient coils} {Manufacture and installation of gradient coils, means for providing mechanical support to parts of the gradient-coil
33/385 33/3852 33/3854 33/3856	 using permanent magnets using gradient magnetic field coils Gradient amplifiers; means for controlling the application of a gradient magnetic field to the sample, e.g. a gradient signal synthesizer} {means for active and/or passive vibration damping or acoustical noise suppression in gradient magnet coil systems} {Means for cooling the gradient coils or thermal shielding of the gradient coils} {Manufacture and installation of gradient coils, means for providing mechanical

22/207	
33/387	Compensation of inhomogeneities
33/3873	• • • • • using ferromagnetic bodies {; Passive shimming}
33/3875	•••• using correction coil assemblies, e.g. active shimming
33/389	• • • Field stabilisation {, e.g. by field
	measurements and control means or indirectly by current stabilisation}
33/42	• • • Screening
33/421	• • • of main or gradient magnetic field
33/4215	•••• {of the gradient magnetic field, e.g. using
	passive or active shielding of the gradient magnetic field}
33/422	of the radio frequency field
33/44	• using nuclear magnetic resonance [NMR] (<u>G01R 33/24, G01R 33/62</u> take precedence)
33/441	• • {Nuclear Quadrupole Resonance [NQR]
	Spectroscopy and Imaging}
33/443	{Assessment of an electric or a magnetic field,
	e.g. spatial mapping, determination of a B0 drift or dosimetry}
33/445	• • • {MR involving a non-standard magnetic field
	B0, e.g. of low magnitude as in the earth's
	magnetic field or in nanoTesla spectroscopy,
	comprising a polarizing magnetic field for pre- polarisation, B0 with a temporal variation of
	its magnitude or direction such as field cycling
	of B0 or rotation of the direction of B0, or
	spatially inhomogeneous B0 like in fringe-field
22/11/	MR or in stray-field imaging}
33/446	• • • {Multifrequency selective RF pulses, e.g. multinuclear acquisition mode (spatially
	selective RF pulses <u>G01R 33/4833</u>)}
33/448	• • • {Relaxometry, i.e. quantification of relaxation
	times or spin density (G01R 33/50 takes
22/16	precedence)}
33/46 33/4608	NMR spectroscopy {RF excitation sequences for enhanced
55/4000	detection, e.g. NOE, polarisation transfer,
	selection of a coherence transfer pathway}
33/4616	• • • • {using specific RF pulses or specific
	modulation schemes, e.g. stochastic
	excitation, adiabatic RF pulses, composite pulses, binomial pulses, Shinnar-le-Roux
	pulses, spectrally selective pulses not being
	used for spatial selection}
33/4625	• • • • {Processing of acquired signals, e.g.
	elimination of phase errors, baseline fitting,
33/4633	<pre>chemometric analysis} {Sequences for multi-dimensional NMR}</pre>
33/4633	Sequences for NMR spectroscopy of
55/4041	samples with ultrashort relaxation times such
22/1/5	as solid samples}
33/465	• • • • applied to biological material, e.g. <u>in vitro</u> testing
33/48	•••• NMR imaging systems
33/4802	{Travelling-wave MR}
33/4804	• • • • {Spatially selective measurement of
22/4007	temperature or pH}
33/4806	{Functional imaging of brain activation}
33/4808	• • • • {Multimodal MR, e.g. MR combined with positron emission tomography [PET], MR
	combined with ultrasound or MR combined
	with computed tomography [CT]}

33/481	••••• {MR combined with positron emission tomography [PET] or single photon emission computed tomography [SPECT]}
33/4812	• • • • {MR combined with X-ray or computed tomography [CT]}
33/4814	• • • • {MR combined with ultrasound}
33/4816	• • • • {NMR imaging of samples with ultrashort
	relaxation times such as solid samples, e.g. MRI using ultrashort TE [UTE], single point imaging, constant time imaging}
33/4818	• • • • {MR characterised by data acquisition along a specific k-space trajectory or by the temporal order of k-space coverage, e.g. centric or segmented coverage of k-space}
33/482	•••• {using a Cartesian trajectory}
33/4822	• • • • • {in three dimensions}
33/4824	•••• {using a non-Cartesian trajectory}
33/4826	• • • • • {in three dimensions}
33/4828	• • • • {Resolving the MR signals of different chemical species, e.g. water-fat imaging}
33/483	• • • • with selection of signals or spectra from particular regions of the volume, e.g. <u>in vivo</u> spectroscopy
33/4831	••••• {using B1 gradients, e.g. rotating frame techniques, use of surface coils}
33/4833	{using spatially selective excitation of the volume of interest, e.g. selecting non- orthogonal or inclined slices}
33/4835	••••• {of multiple slices}
33/4836	••••••••••••••••••••••••••••••••••••••
	selective in more than one spatial dimension, e.g. a 2D pencil-beam excitation pulse}
33/4838	•••• {using spatially selective suppression or saturation of MR signals}
33/485	 based on chemical shift information {[CSI] or spectroscopic imaging, e.g. to acquire the spatial distributions of metabolites}
33/50	 based on the determination of relaxation times {, e.g. T1 measurement by IR sequences; T2 measurement by multiple- echo sequences}
33/54	• • • • Signal processing systems, e.g. using pulse
	sequences {; Generation or control of pulse sequences; Operator console}
33/543	••••• {Control of the operation of the MR system, e.g. setting of acquisition
	parameters prior to or during MR data acquisition, dynamic shimming, use of one or more scout images for scan plane prescription (<u>G01R 33/546</u> takes precedence)}
33/546	••••• {Interface between the MR system and the user, e.g. for controlling the operation of the MR system or for the design of pulse sequences}
33/56	Image enhancement or correction, e.g. subtraction or averaging techniques {, e.g. improvement of signal-to-noise ratio and resolution}

33/5601	••••• {involving use of a contrast agent for contrast manipulation, e.g. a paramagnetic, super-paramagnetic ferromagnetic or hyperpolarised co agent}	
33/5602	••••••••••••••••••••••••••••••••••••••	e
33/5604	••••• {Microscopy; Zooming}	
33/5605	••••• {by transferring coherence or polarization from a spin species to another, e.g. creating magnetizatio transfer contrast [MTC], polarizati transfer using nuclear Overhauser enhancement [NOE]}	
33/5607	••••• {by reducing the NMR signal of	
	a particular spin species, e.g. of a	
	chemical species for fat suppression of a moving spin species for black- imaging}	
33/5608	{Data processing and visualization	l
	specially adapted for MR, e.g. for	
	feature analysis and pattern recogn	
	on the basis of measured MR data,	
	segmentation of measured MR dat	
	edge contour detection on the basis of measured MR data, for enhancing	
	measured MR data, for emailed measured MR data in terms of sign	
	noise ratio by means of noise filter	
	or apodization, for enhancing measured	
	MR data in terms of resolution by	
	means for deblurring, windowing,	zero
	filling, or generation of gray-scale	
	images, colour-coded images or in	
	displaying vectors instead of pixel	
	(image data processing or generation	on, in
22/561	general <u>G06T</u>)}	
33/561	fast acquiring systems, e.g. using e	
	planar pulse sequences	cno-
33/5611	· · · · · · · {Parallel magnetic resonance	
55/5011	imaging, e.g. sensitivity encodin	a
	[SENSE], simultaneous acquisit	
	of spatial harmonics [SMASH],	
	unaliasing by Fourier encoding	of
	the overlaps using the temporal	
	dimension [UNFOLD], k-t-broa	d-
	use linear acquisition speed-up	
	technique [k-t-BLAST], k-t-SEN	
	(structural details of arrays of su	D-
33/5612	coils <u>G01R 33/3415</u>)}	рг
55/5012	pulse transmission using a plu of independent transmission channels}	
33/5613	• • • • • • • • {Generating steady state signals	e 0
55/5015	low flip angle sequences [FLAS	
33/5614	• • • • • • • • • • { using a fully balanced steady	
20,0011	state free precession [bSSFP]	
	sequence, e.g. trueFISP}	•
	,	

33/5615	{Echo train techniques acquiring plural, differ echo signals after one e.g. using gradient refo planar imaging [EPI], in rapid acquisition wi enhancement [RARE] both RF and gradient r in gradient and spin ec [GRASE]}	ently encoded, RF excitation, ocusing in echo RF refocusing th relaxation or using efocusing
33/5616	• • • • • {using gradient refo EPI}	cusing, e.g.
33/5617	{using RF refocusin	g, e.g. RARE}
33/5618	••••• {using both RF and	
	refocusing, e.g. GRA	
33/5619	••••• {by temporal sharing of keyhole, block regional scheme for k-Space [B]	of data, e.g. l interpolation RISK]}
33/563	of moving material, e.g. angiography	flow contrast
33/56308	{Characterization of m	otion or flow;
	Dynamic imaging}	
33/56316	{involving phase co techniques}	ntrast
33/56325	••••• {Cine imaging}	
33/56333	••••• {Involving spatial m	odulation
	of the magnetization an imaged region, e. modulation of magn [SPAMM] tagging (imaging based on ar tagging <u>G01R 33/56</u>	g. spatial etization perfusion terial spin
33/56341	••••• {Diffusion imaging}	
33/5635	Angiography, e.g. con angiography [CE-MRA flight angiography [CC	A] or time-of-
33/56358	••••• {Elastography}	
33/56366	• • • • • {Perfusion imaging}	
33/56375	{Intentional motion of during MR, e.g. movin imaging}	
33/56383	(involving motion o as a whole, e.g. mult MR with continuous	tistation MR or
33/56391	••••••••••••••••••••••••••••••••••••••	to another part
33/565	• • • • Correction of image distored to magnetic field inhomo	
33/56509	{due to motion, display flow, e.g. gradient mon	nent nulling
33/56518	(G01R 33/567 takes pr {due to eddy currents, switching of the gradie field}	e.g. caused by
	<u>NOTE</u>	
	This group only cov of artifacts caused b non-linearity	
33/56527	••••• {due to chemical shift	effects }
33/56536	{due to magnetic susce	
	variations}	× .7

33/56545	••••••••••••••••••••••••••••••••••••••
33/56554	 artefacts, phase aliasing artefacts}
33/56563	 one RF excitation, e.g. correction for readout gradients of alternating polarity in EPI}
33/56572	or spatial inhomogeneity of B0 (G01R 33/56509, G01R 33/56518, G01R 33/56536 take precedence)} {caused by a distortion of a gradient magnetic field, e.g. non-linearity of a gradient magnetic field (G01R 33/56509, G01R 33/56518,
33/56581	<u>G01R 33/56536</u> take precedence)} {due to Maxwell fields, i.e.
33/5659	concomitant fields} {caused by a distortion of the RF magnetic field, e.g. spatial inhomogeneities of the RF magnetic field (<u>G01R 33/56509</u> , <u>G01R 33/56518</u> , <u>G01R 33/56536</u> take
33/567	
33/5673	{Gating or triggering based on a physiological signal other than an MR signal, e.g. ECG gating or motion monitoring using optical systems for monitoring the motion of a fiducial marker }
33/5676	• • • • • • • {Gating or triggering based on an MR signal, e.g. involving one or more navigator echoes for motion monitoring and correction}
33/58	•••• Calibration of imaging systems, e.g. using test probes {, Phantoms; Calibration objects or fiducial markers such as active or passive RF coils surrounding an MR active material}
33/583	••••• {Calibration of signal excitation or detection systems, e.g. for optimal RF excitation power or frequency (G01R 33/246 takes precedence)}
33/586	••••• {for optimal flip angle of RF pulses}
33/60	• using electron paramagnetic resonance (<u>G01R 33/24</u> , <u>G01R 33/62</u> take precedence)
33/62	• using double resonance (<u>G01R 33/24</u> takes precedence)
33/64	• using cyclotron resonance (<u>G01R 33/24</u> takes precedence)
35/00	Testing or calibrating of apparatus covered by the other groups of this subclass
35/002	• {of cathode ray oscilloscopes}
35/005	• {Calibrating; Standards or reference devices, e.g. voltage or resistance standards, "golden" references
35/007	 (G01R 33/0035, G01R 35/002 take precedence)} (Standards or reference devices, e.g. voltage or resistance standards, "golden references"}

35/02	• of auxiliary devices, e.g. of instrument transformers
	according to prescribed transformation ratio, phase
	angle, or wattage rating
35/04	• of instruments for measuring time integral of power
	or current

35/06 • • by stroboscopic methods